

EE 330

Lecture 29

Bipolar Processes

- Device Sizes
- Parasitic Devices
 - JFET
 - Thyristors

Thyristors

- SCR – Basic operation

Exam Schedule

Exam 1	Friday Sept 24
Exam 2	Friday Oct 22
Exam 3	Friday Nov 19
Final	Tues Dec 14 12:00 p.m.

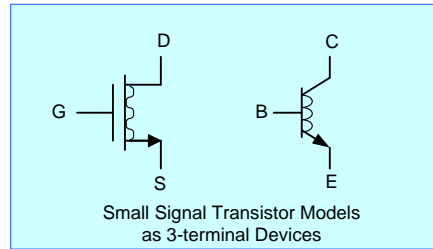
Photo courtesy of the director of the National Institute of Health (NIH)



As a courtesy to fellow classmates, TAs, and the instructor

Wearing of masks during lectures and in the laboratories for this course would be appreciated irrespective of vaccination status

Basic Amplifier Structures



	MOS			BJT		
	Common	Input	Output	Common	Input	Output
Common Source or Common Emitter	S	G	D	E	B	C
Common Gate or Common Base	G	S	D	B	E	C
Common Drain or Common Collector	D	G	S	C	B	E

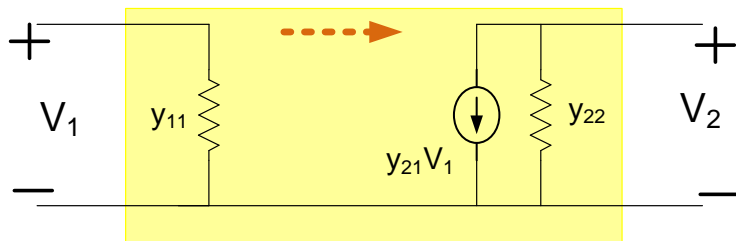
Identification of Input and Output Terminals is not arbitrary

It will be shown that all 3 of the basic amplifiers are useful !

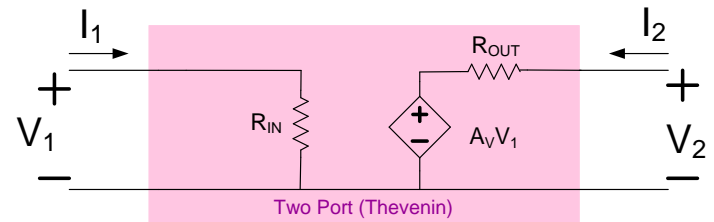
Review From Previous Lecture

Two-port representation of amplifiers

- Amplifier often **unilateral** (signal propagates in only one direction: wlog $y_{12}=0$)
- One terminal is often common
- “Amplifier” parameters often used

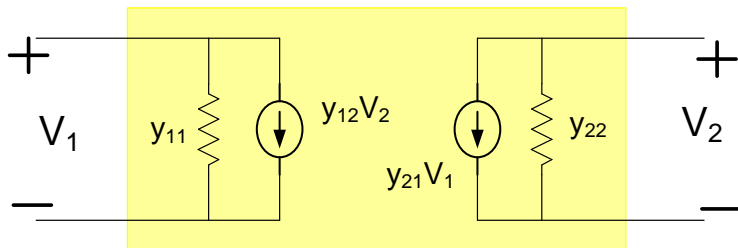


y parameters

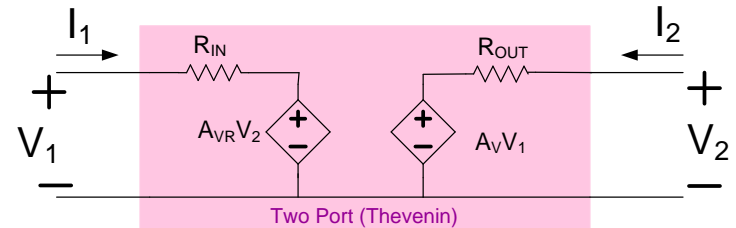


Amplifier parameters

- Amplifier parameters can also be used if not **unilateral**
- One terminal is often common

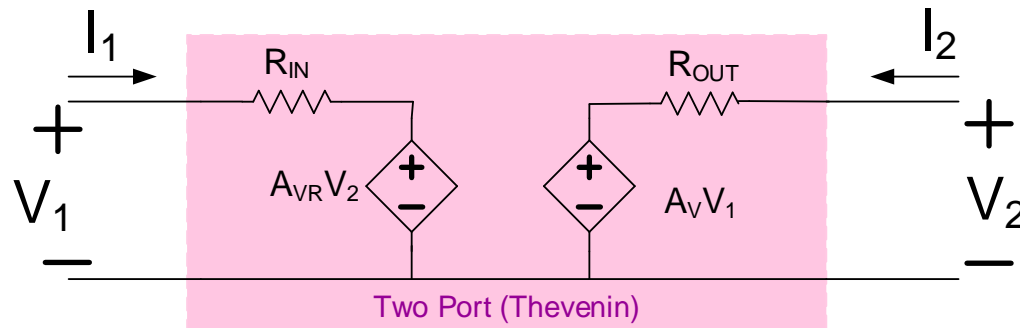


y parameters



Amplifier parameters

Relationship with Dependent Sources ?

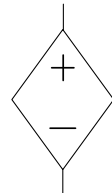


Dependent sources from EE 201

Voltage
Amplifier

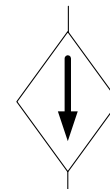
$$v_s = \mu v_x$$

Voltage Dependent
Voltage Source



$$I_s = \alpha v_x$$

Voltage Dependent
Current Source

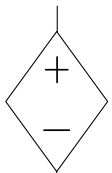


Transconductance
Amplifier

Transresistance
Amplifier

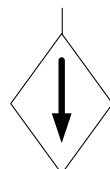
$$v_s = \rho I_x$$

Current Dependent
Voltage Source



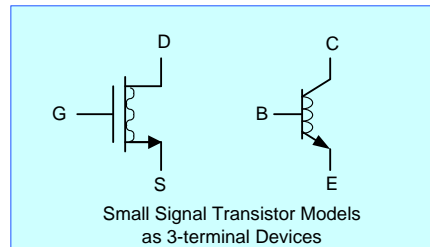
$$I_s = \beta I_x$$

Current Dependent
Current Source



Current
Amplifier

Basic Amplifier Structures



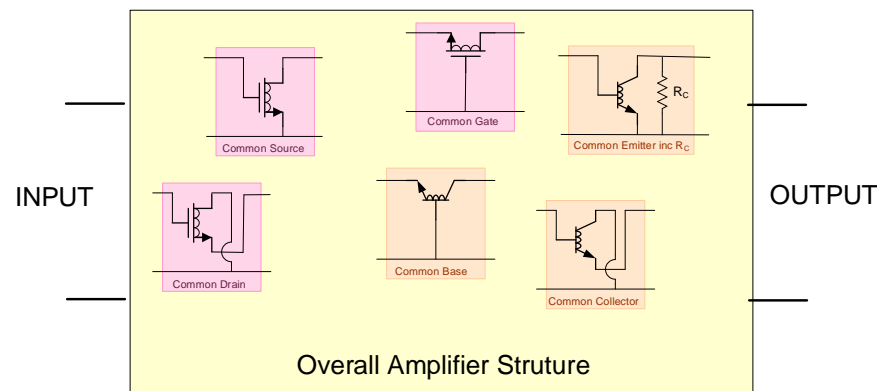
Common Source or Common Emitter

Common Gate or Common Base

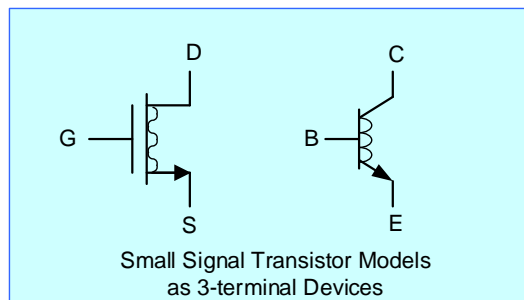
Common Drain or Common Collector

Objectives in Study of Basic Amplifier Structures

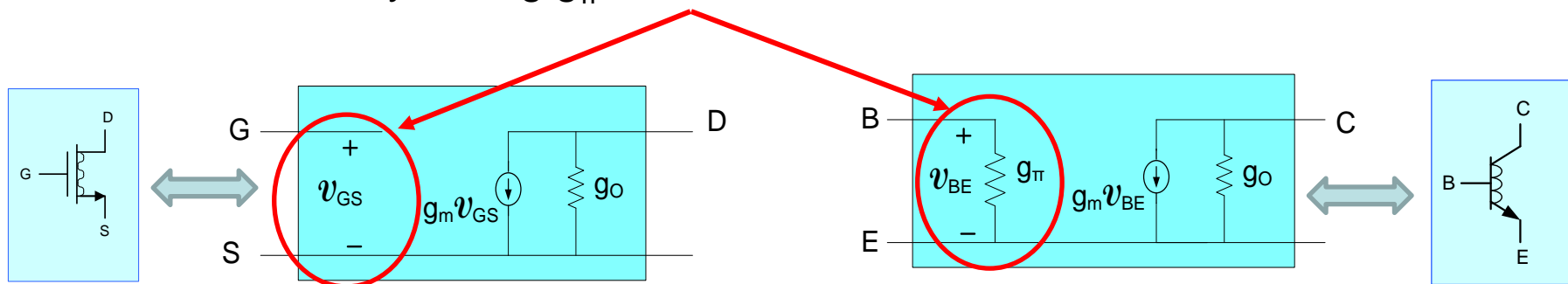
1. Obtain key properties of each basic amplifier
2. Develop method of designing amplifiers with specific characteristics using basic amplifier structures



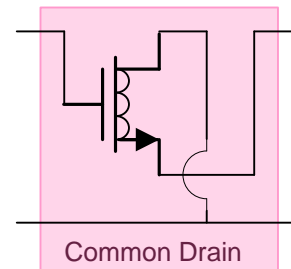
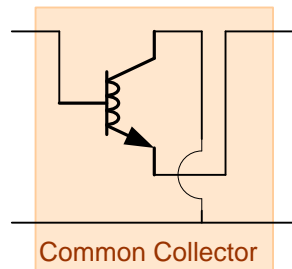
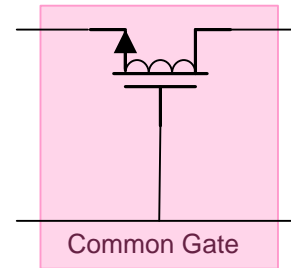
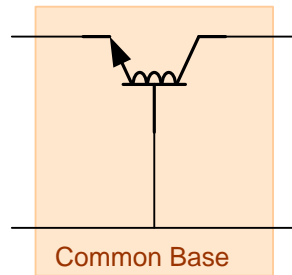
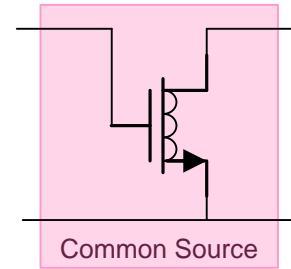
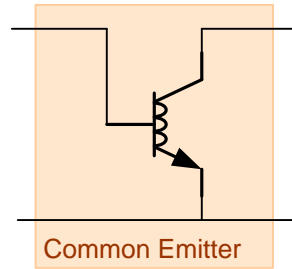
Characterization of Basic Amplifier Structures



- Observe that the small-signal equivalent of any 3-terminal network is a two-port
- Thus to characterize any of the 3 basic amplifier structures, it suffices to determine the two-port equivalent network
- Since small signal model when expressed in terms of small-signal parameters of BJT and MOSFET differ only in the presence/absence of g_{π} term, can analyze the BJT structures and then obtain characteristics of corresponding MOS structure by setting $g_{\pi}=0$

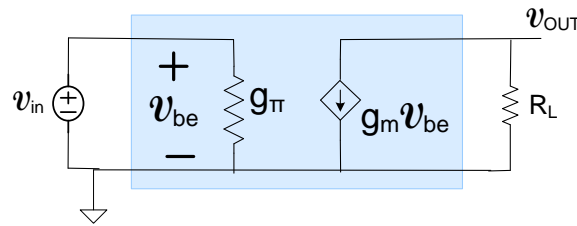
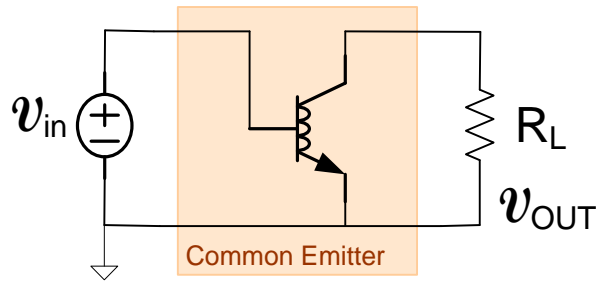


The three basic amplifier types for both MOS and bipolar processes



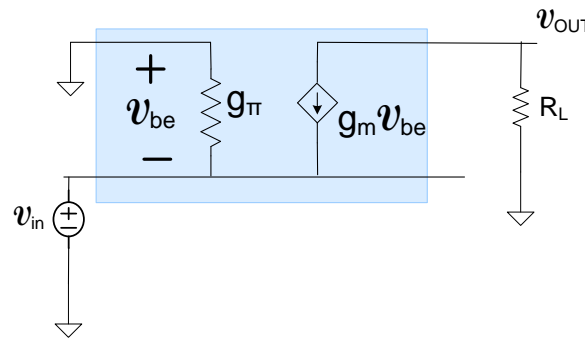
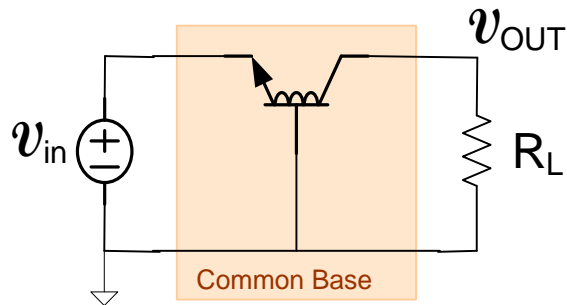
Will focus on the performance of the bipolar structures and then obtain performance of the MOS structures by observation

The three basic amplifier types for both MOS and bipolar processes



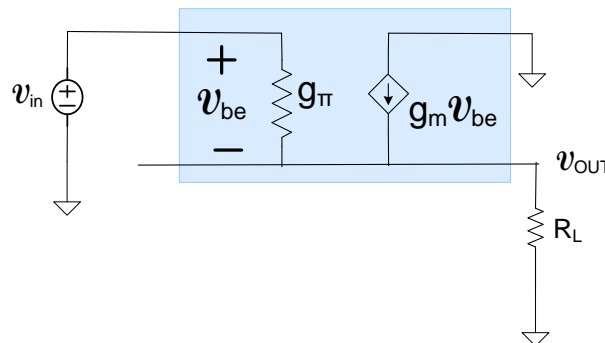
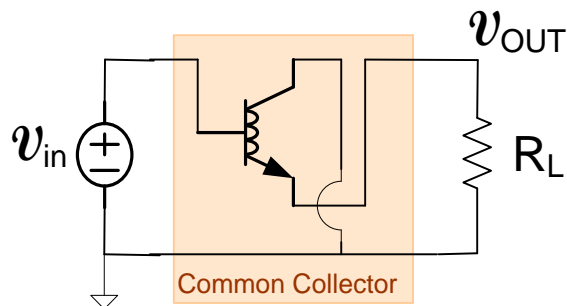
$$\left. \begin{aligned} v_{OUT} &= -g_m R_L v_{be} \\ v_{IN} &= v_{be} \end{aligned} \right\}$$

$$A_V = \frac{v_{OUT}}{v_{IN}} = -g_m R_L$$



$$\left. \begin{aligned} v_{OUT} &= -g_m R_L v_{be} \\ v_{IN} &= -v_{be} \end{aligned} \right\}$$

$$A_V = \frac{v_{OUT}}{v_{IN}} = g_m R_L$$

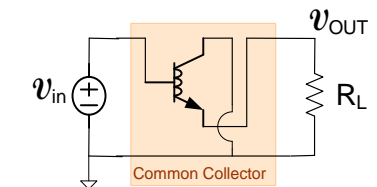
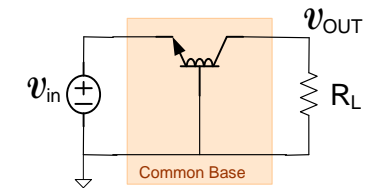
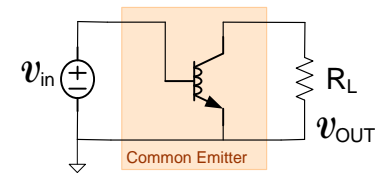
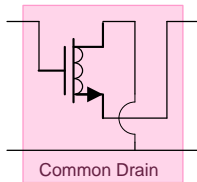
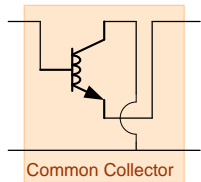
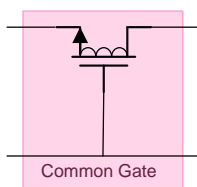
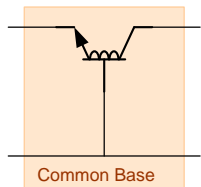
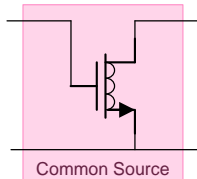
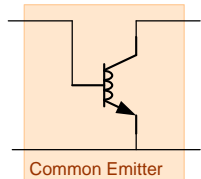


$$\left. \begin{aligned} v_{OUT} &= (g_m + g_\pi) v_{be} R_L \\ v_{IN} &= v_{be} + (g_m + g_\pi) v_{be} R_L \end{aligned} \right\}$$

$$A_V = \frac{v_{OUT}}{v_{IN}} = \frac{(g_m + g_\pi) R_L}{1 + (g_m + g_\pi) R_L} \cong 1$$

- Significantly different gain characteristics for the three basic amplifiers
- There are other significant differences too (R_{IN} , R_{OUT} , ...) as well

The three basic amplifier types for both MOS and bipolar processes



More general models are needed to accommodate biasing, understand performance capabilities, and include effects of loading of the basic structures

Two-port models are useful for characterizing the basic amplifier structures

How can the two-port parameters be obtained for these or any other linear two-port networks?


Topical Coverage Change

Will have several additional lectures on amplifier structures but will temporarily suspend discussion of amplifiers to consider Thyristors

This is being done to get ready for the Thyristor laboratory experiments

Outline

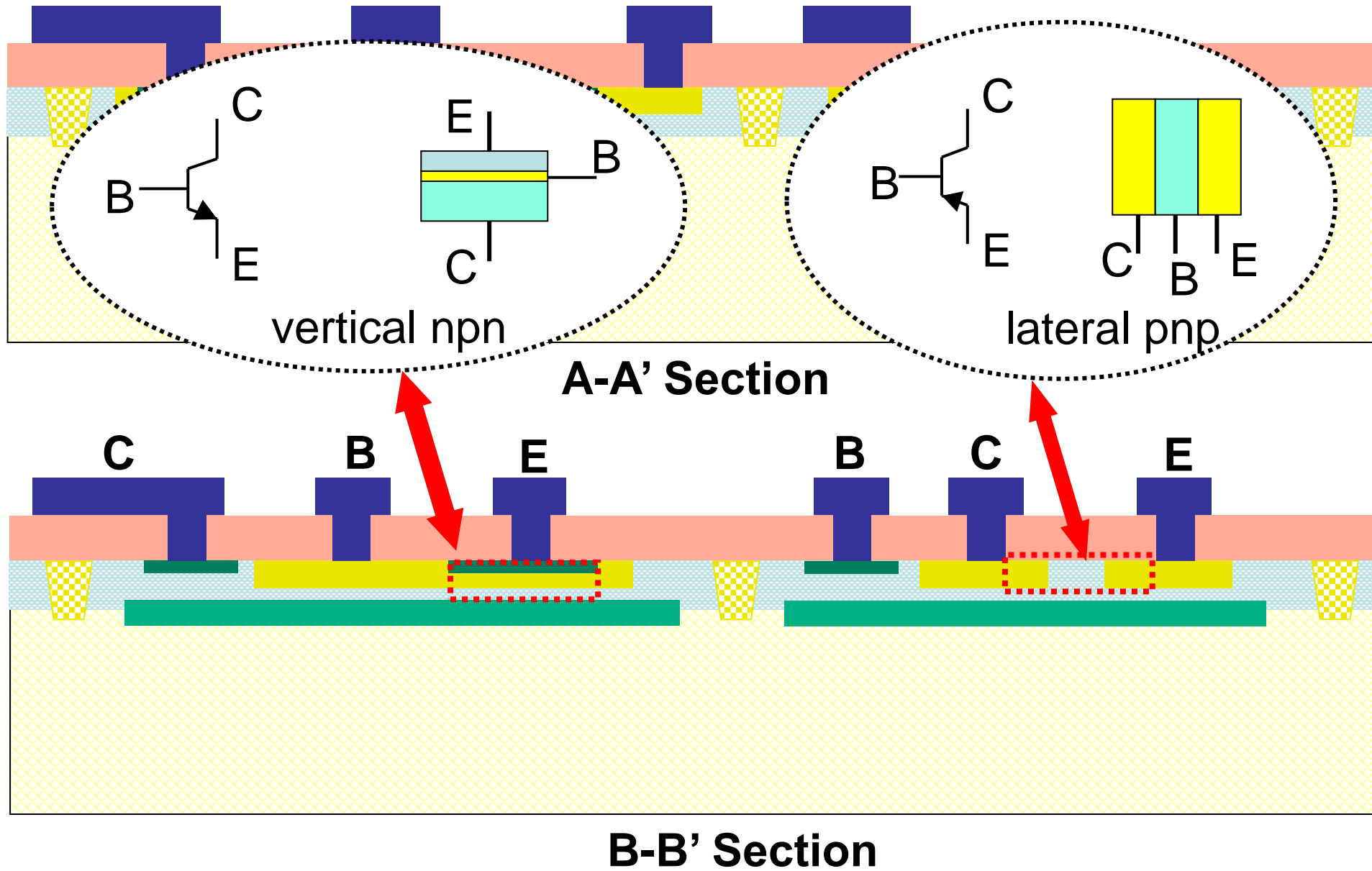
Bipolar Processes

-  • Parasitic Devices in CMOS Processes
- JFET
- Other Junction Devices

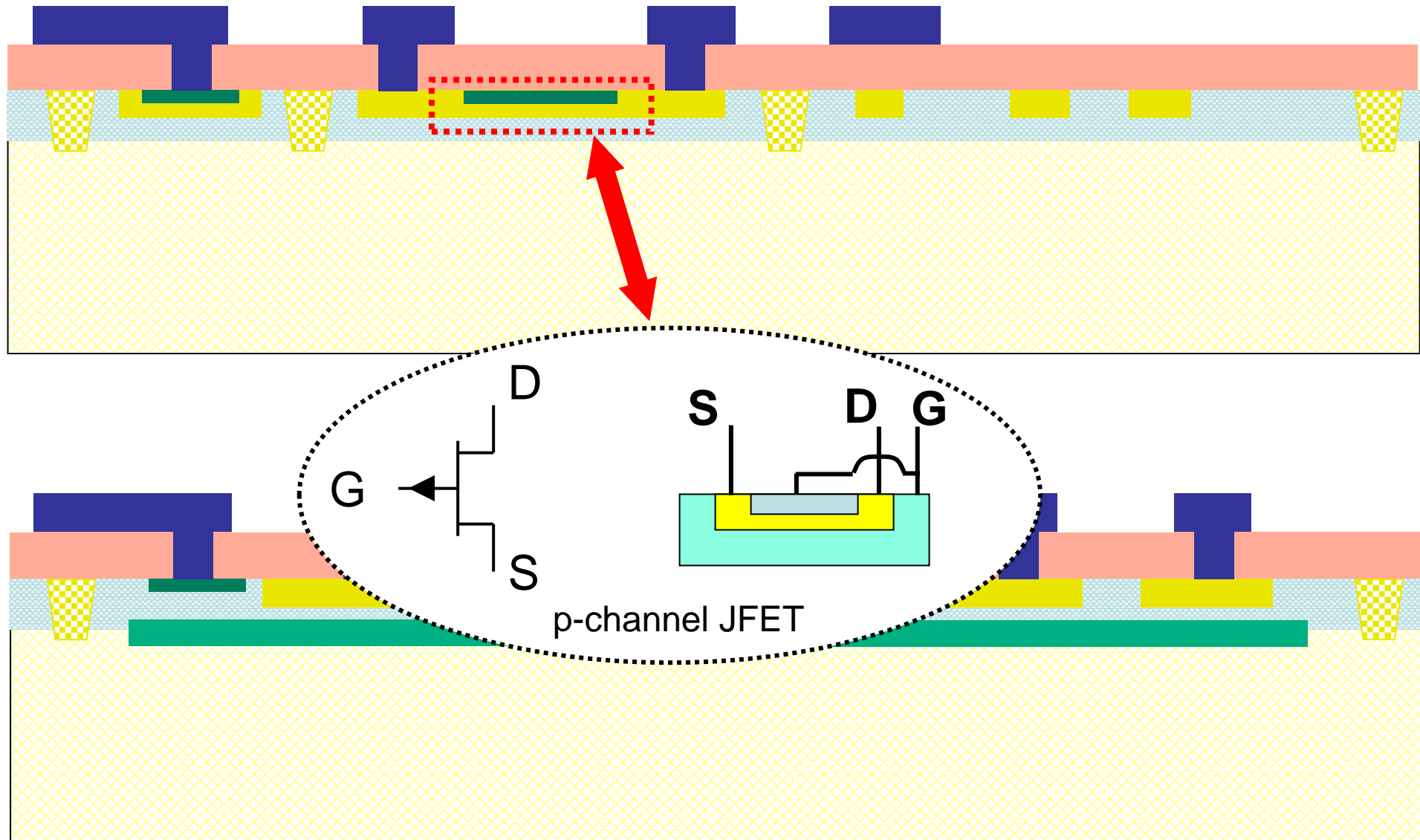
Special Bipolar Processes

- Thyristors
SCR
TRIAC

Review from a Previous Lecture

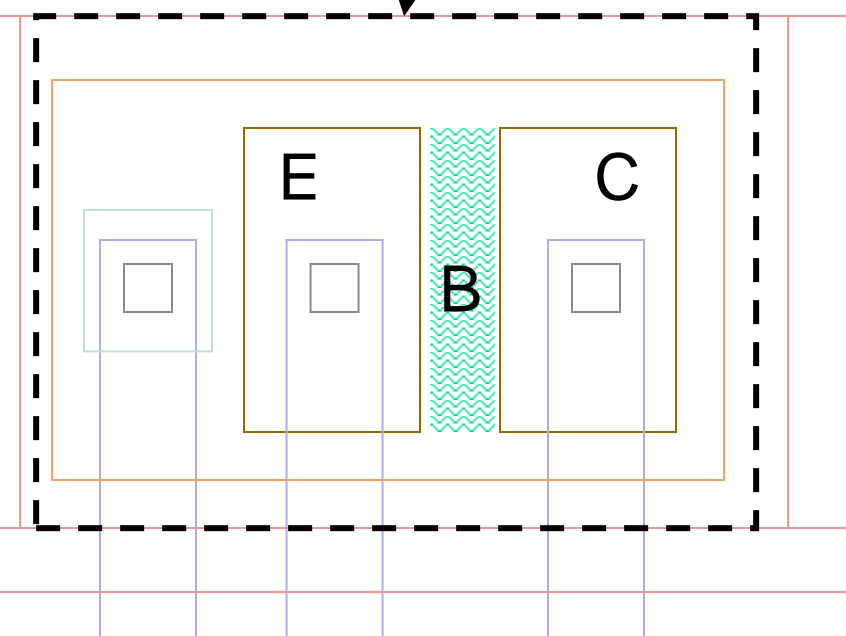
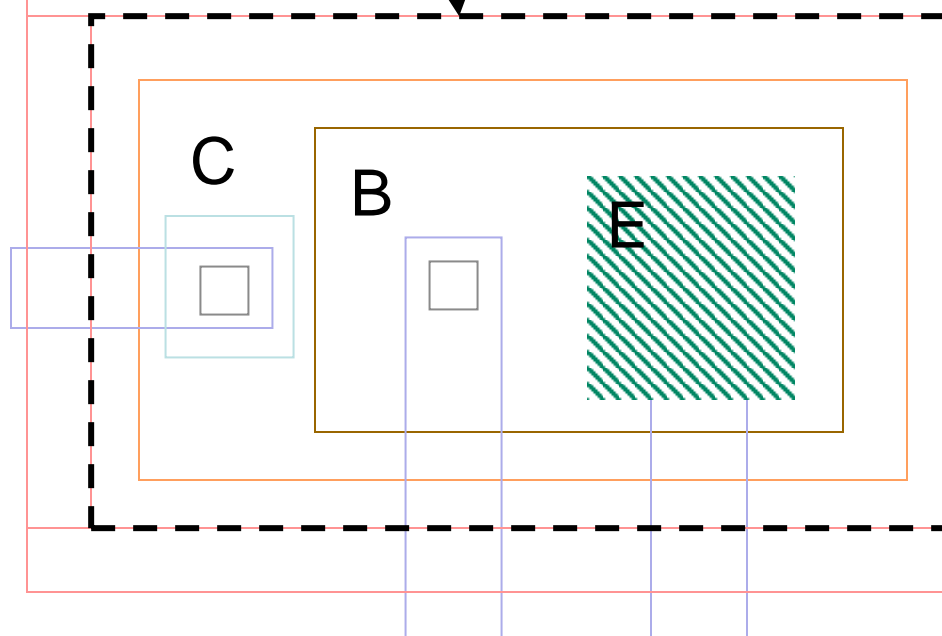
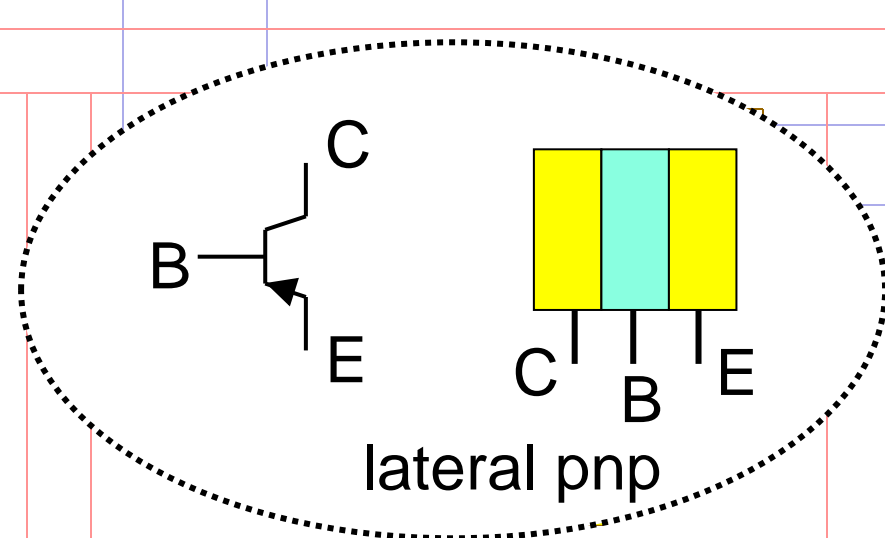
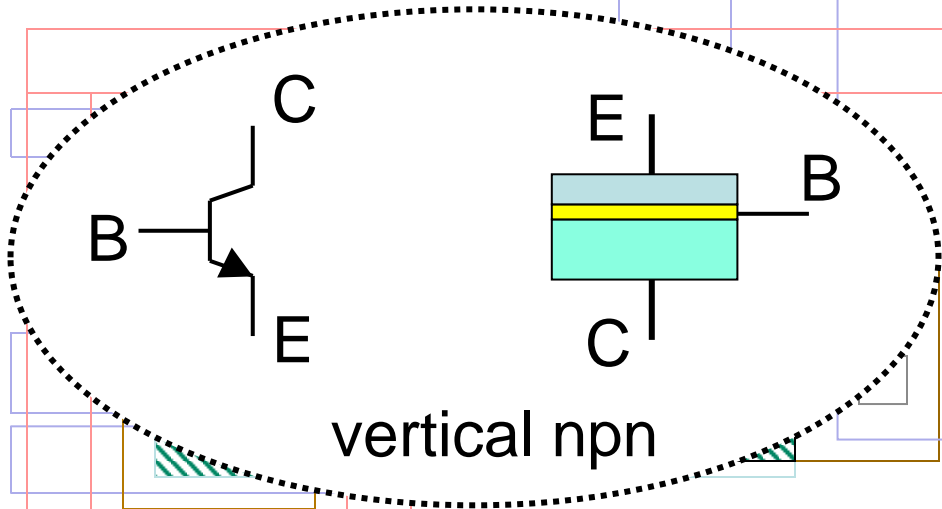


Review from a Previous Lecture



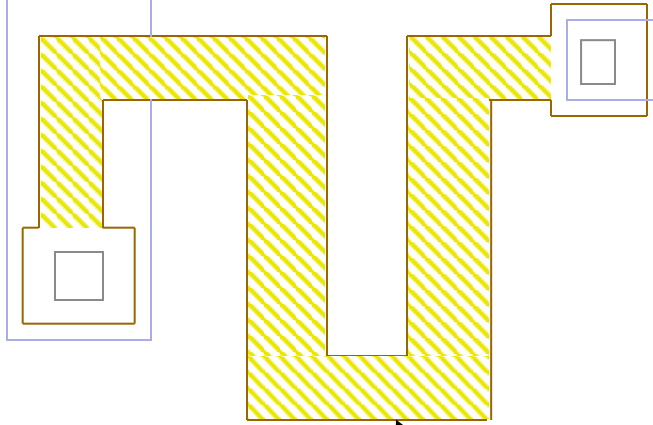
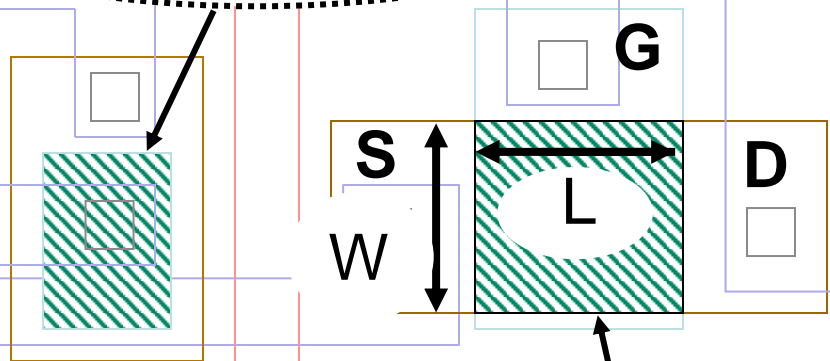
B-B' Section

Review from a Previous Lecture

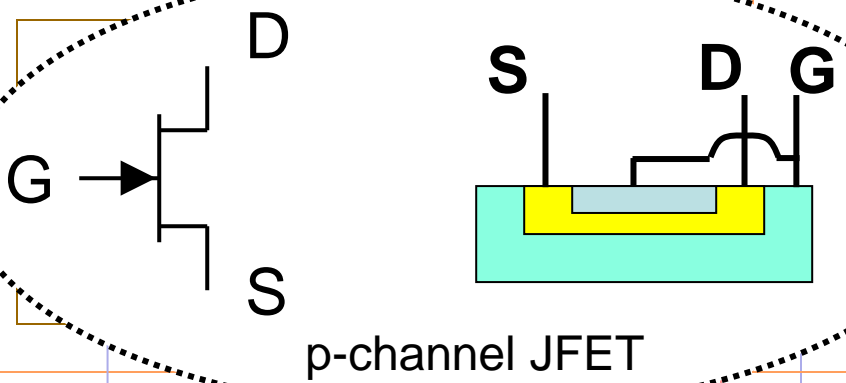


Review from a Previous Lecture

Diode (capacitor)



Resistor



p-channel JFET

Will consider next the JFET but first some additional information about MOS Devices

Enhancement and Depletion MOS Devices

- Enhancement Mode n-channel devices

$$V_T > 0$$

- Enhancement Mode p-channel devices

$$V_T < 0$$

- Depletion Mode n-channel devices

$$V_T < 0$$

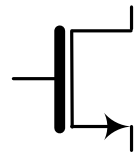
- Depletion Mode p-channel devices

$$V_T > 0$$

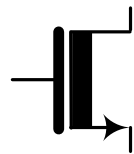
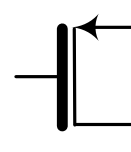
Enhancement and Depletion MOS Devices

n-channel

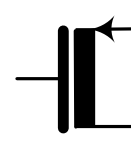
p-channel



Enhancement



Depletion



- Depletion mode devices require only one additional mask step
- Older n-mos and p-mos processes usually had a depletion device and an enhancement device
- Depletion devices usually not available in CMOS because applications usually do not justify the small increasing costs in processing
- The threshold voltage of either n-channel or p-channel devices is adjusted to a desired value by doing a channel implant before gate oxide is applied

Outline

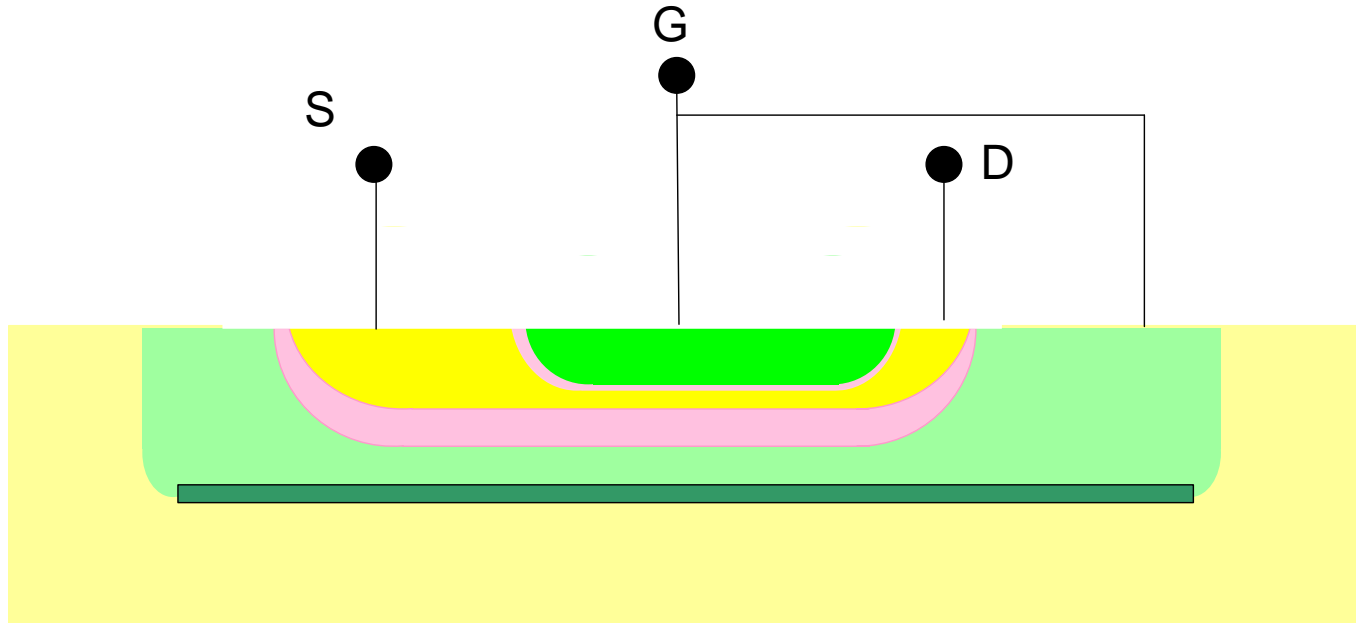
Bipolar Processes

- Parasitic Devices in CMOS Processes
-  • JFET
- Other Junction Devices

Special Bipolar Processes

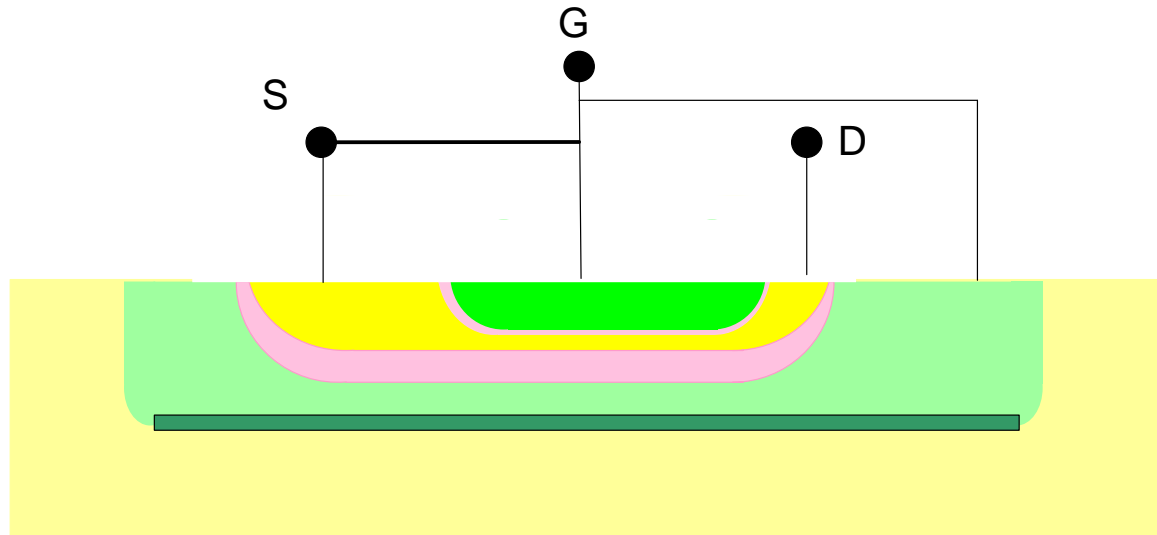
- Thyristors
SCR
TRIAC

The JFET



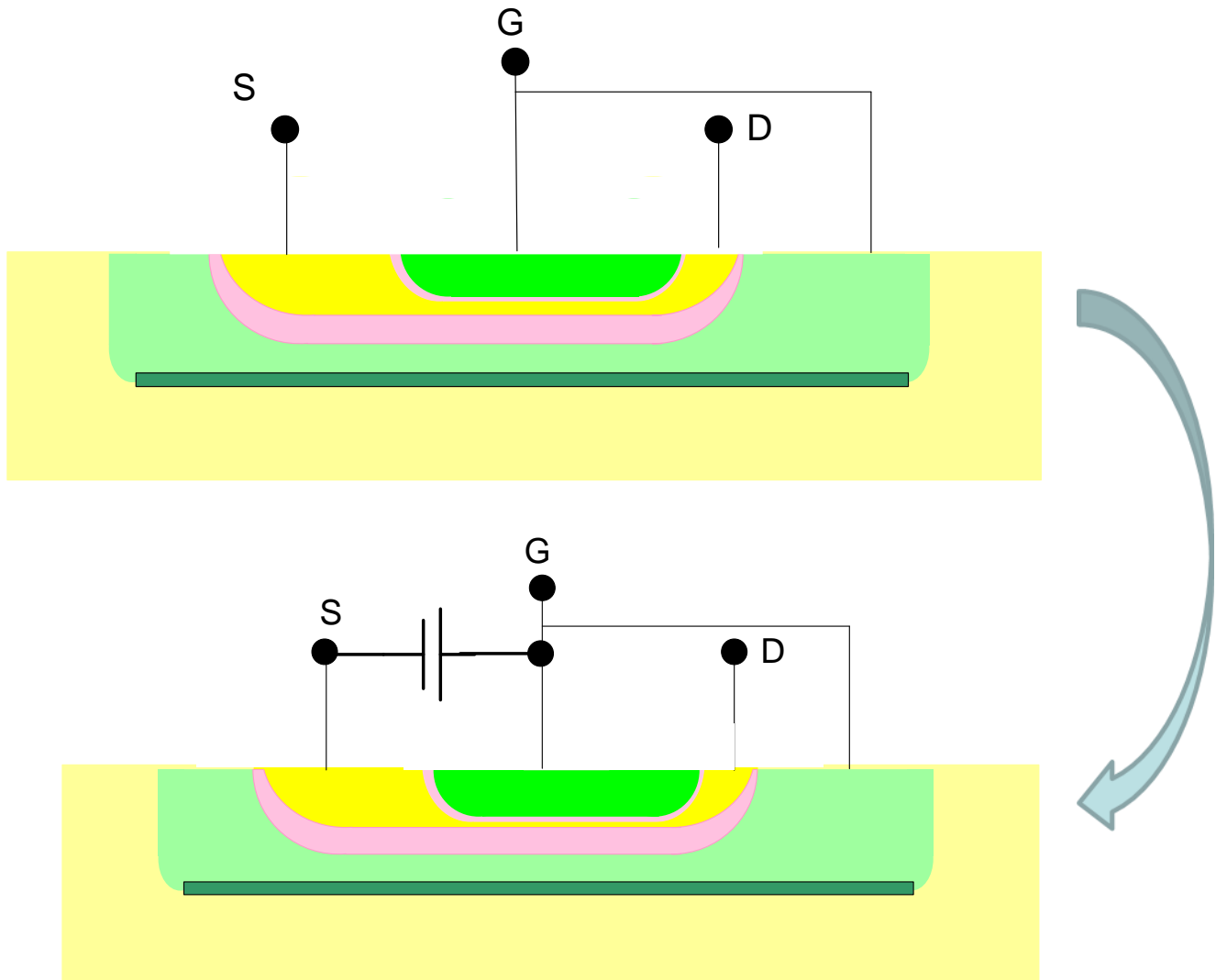
- Gate is both above and below channel
- With no bias, channel exists between D and S

The JFET



With $V_{GS}=0$, channel exists under gate between D and S

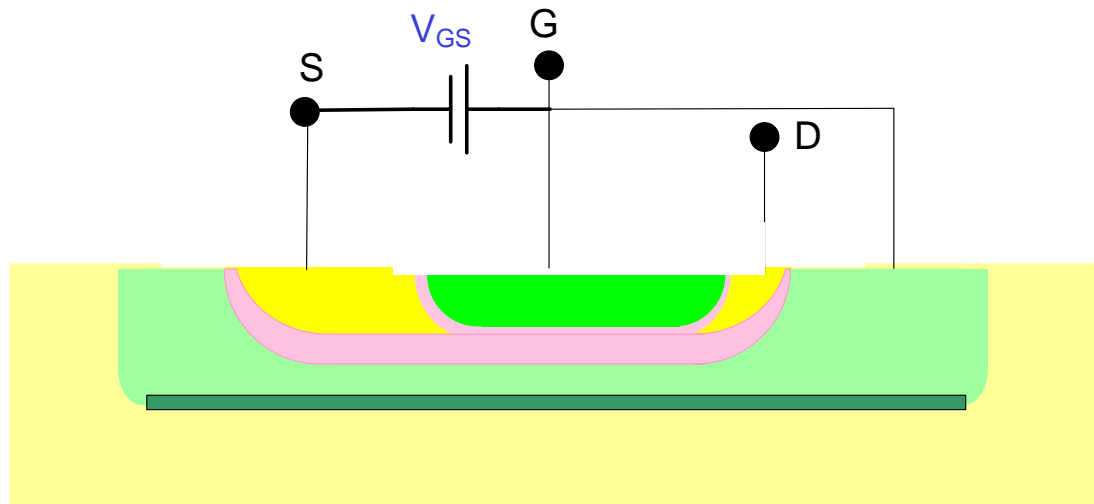
The JFET



Under small reverse bias (depletion region widens and channel thins)

The JFET

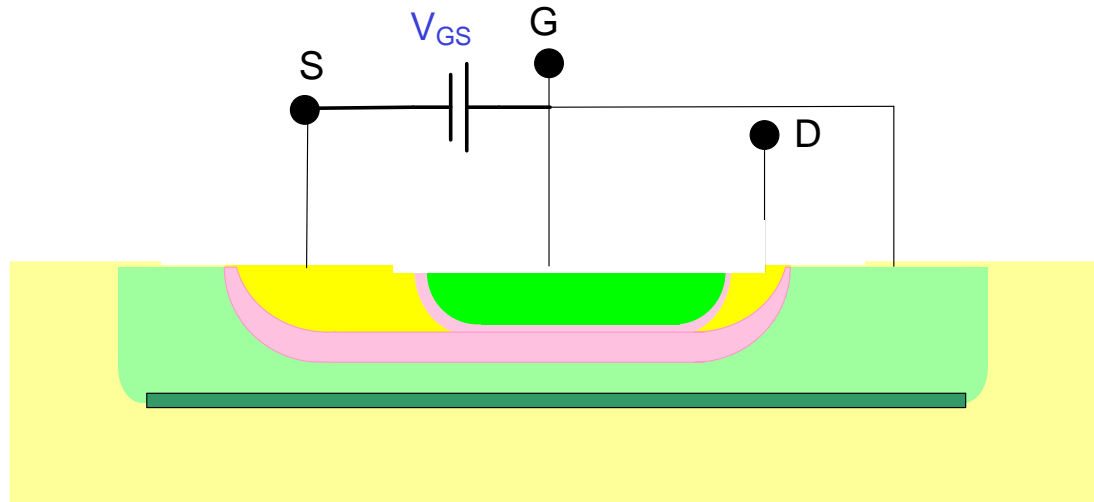
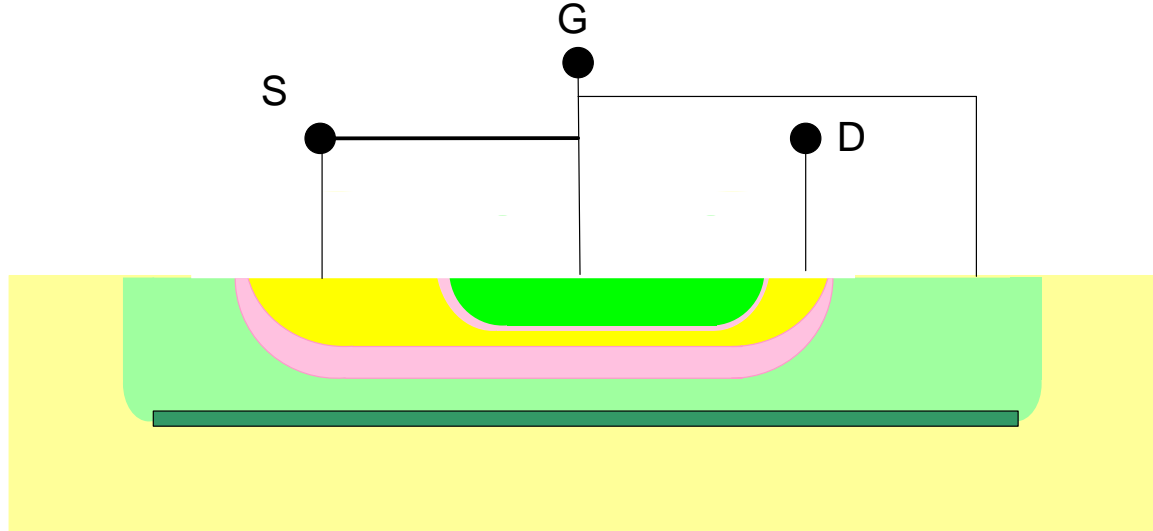
With $V_{GS}=0$, channel exists under gate between D and S



Under sufficiently large reverse bias (depletion region widens and channel disappears - "pinches off")

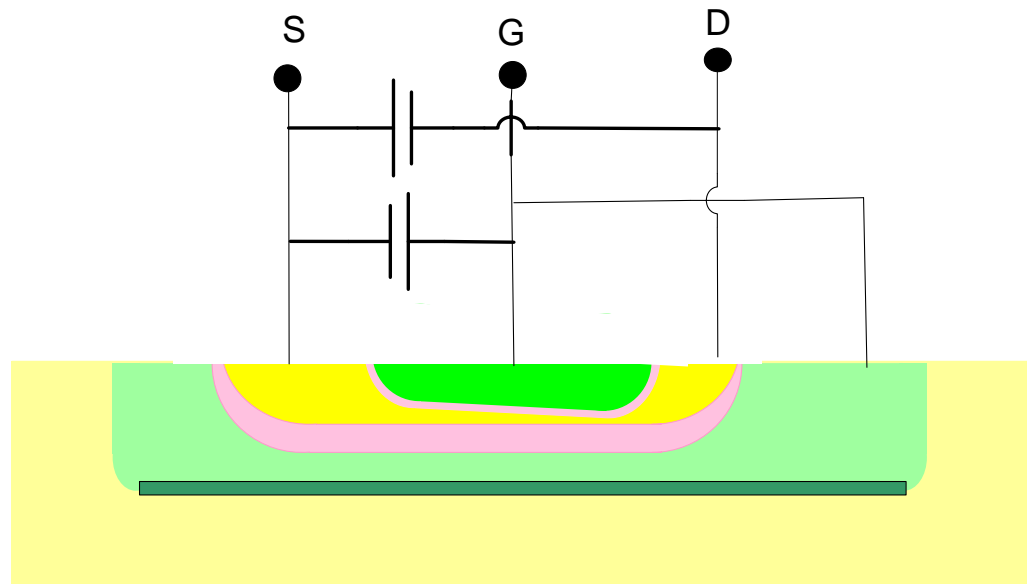
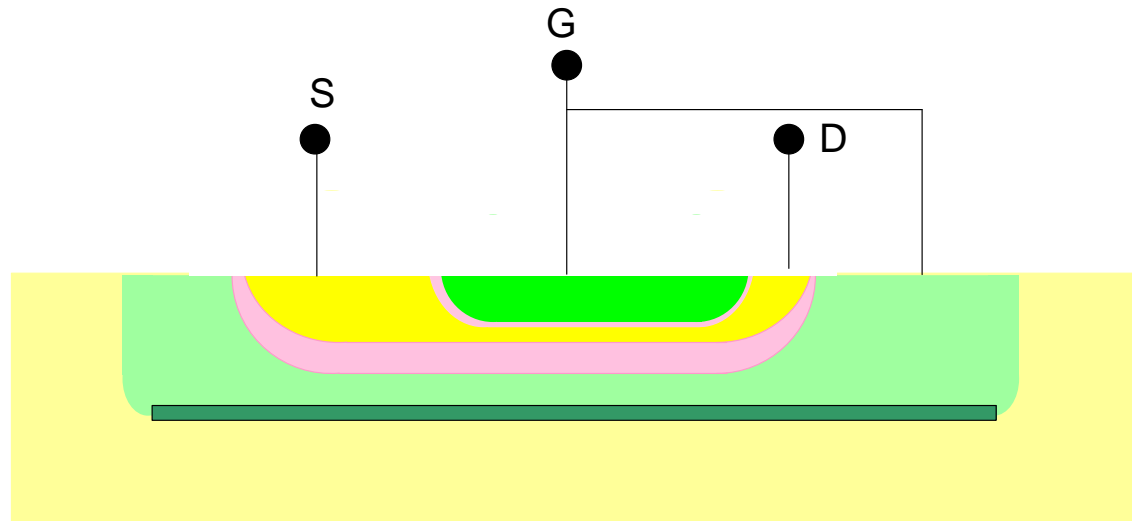


The JFET



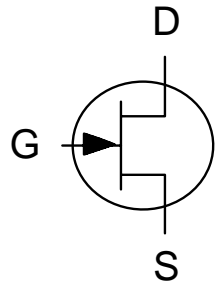
Under sufficiently large reverse bias (depletion region widens and channel disappears - "pinches off")

The JFET

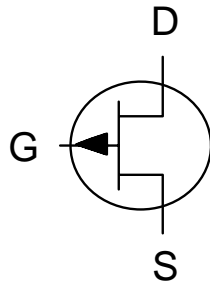


Under small reverse bias and large negative V_{DS} (channel pinches off)

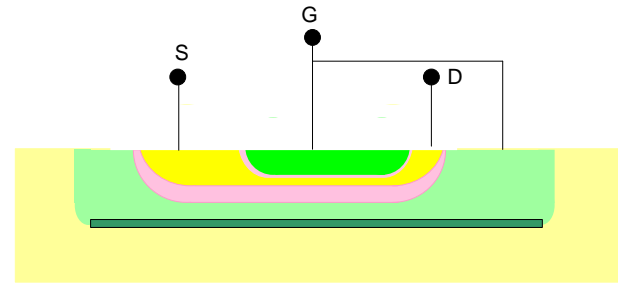
The JFET



n-channel



p-channel



p-channel JFET

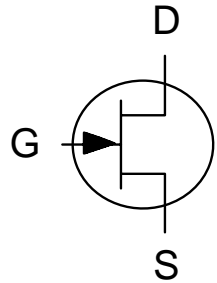
Square-law model of p-channel JFET

$$I_D = \begin{cases} 0 & V_{GS} > V_P \\ \frac{2I_{DSSp}}{V_P^2} \left(V_{GS} - V_P - \frac{V_{DS}}{2} \right) V_{DS} & -0.3 < V_{GS} < V_P \quad V_{GS} + 0.3 > V_{DS} > V_{GS} - V_P \\ I_{DSSp} \left(1 - \frac{V_{GS}}{V_P} \right)^2 & -0.3 < V_{GS} < V_P \quad V_{DS} < V_{GS} - V_P \end{cases}$$

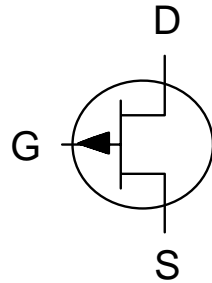
(I_{DSSp} carries negative sign)

- Functionally identical to the square-law model of MOSFET
- Parameters I_{DSS} and V_P characterize the device
- I_{DSS} proportional to W/L where W and L are width and length of n+ diff
- V_P is negative for n-channel device, positive for p-channel device thus JFET is depletion mode device
- Must not forward bias GS junction by over about 300mV or excessive base current will flow (red constraint)
- Widely used as input stage for bipolar op amps

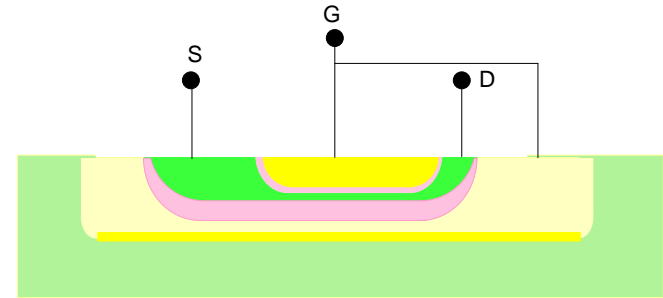
The JFET



n-channel



p-channel



n-channel JFET
(not available in this process)

Square-law model of n-channel JFET

$$I_D = \begin{cases} 0 & V_{GS} < V_P \\ \frac{2I_{DSS}}{V_P^2} \left(V_{GS} - V_P - \frac{V_{DS}}{2} \right) V_{DS} & 0.3 > V_{GS} > V_P \quad V_{GS} - 0.3 < V_{DS} < V_{GS} - V_P \\ I_{DSS} \left(1 - \frac{V_{GS}}{V_P} \right)^2 & 0.3 > V_{GS} > V_P \quad V_{DS} > V_{GS} - V_P \end{cases}$$

- Functionally identical to the square-law model of MOSFET
- Parameters I_{DSS} and V_P characterize the device
- I_{DSS} proportional to W/L where W and L are width and length of n+ diff
- V_P is negative for n-channel device, positive for p-channel device thus JFET is depletion mode device
- Must not forward bias GS junction by over about 300mV or excessive base current will flow (red constraint)
- Widely used as input stage for bipolar op amps

Outline

Bipolar Processes

- Parasitic Devices in CMOS Processes
- JFET

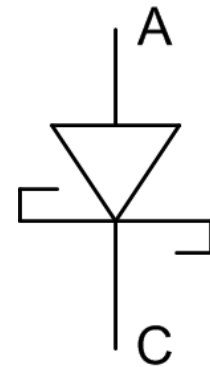
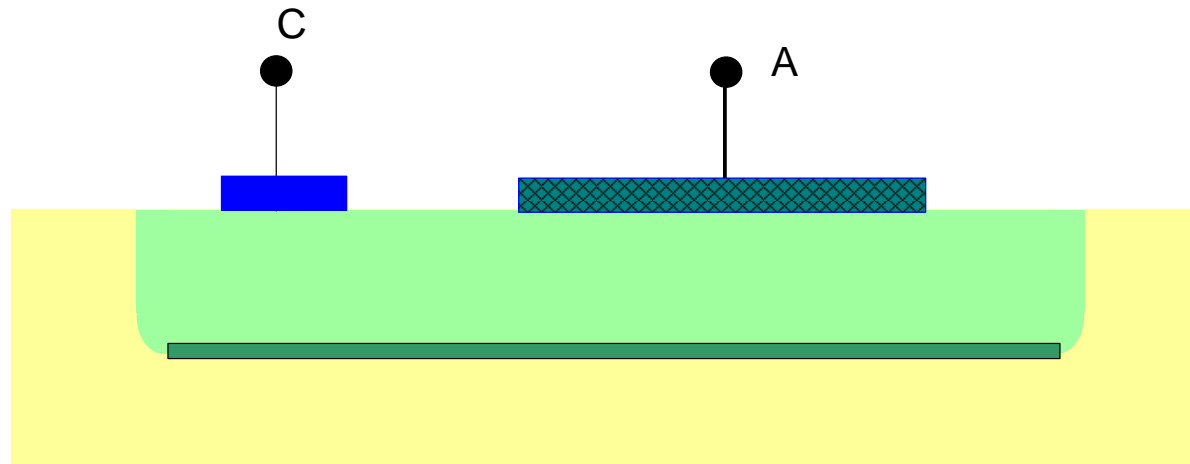


Other Junction Devices

Special Bipolar Processes

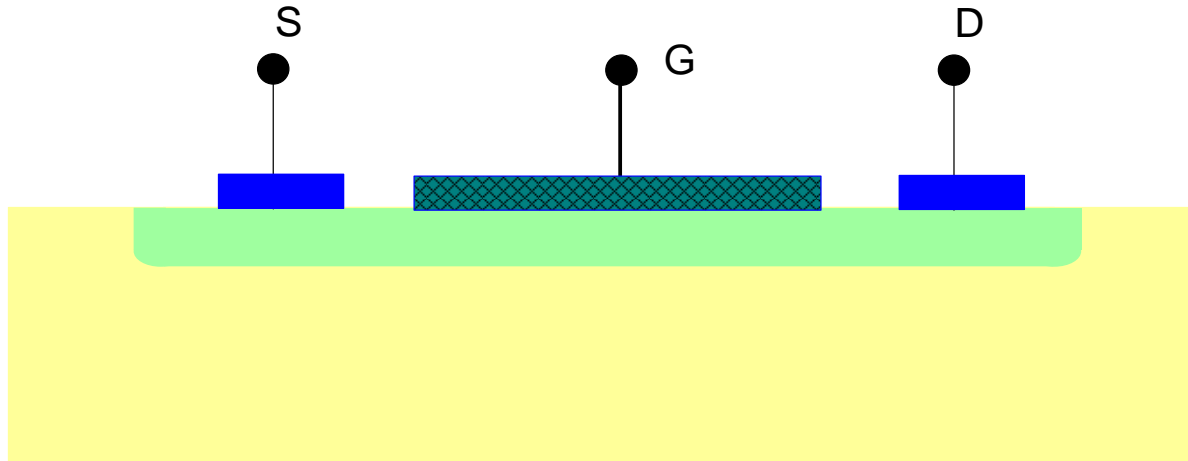
- Thyristors
SCR
TRIAC

The Schottky Diode



- Metal-Semiconductor Junction
- One contact is ohmic, other is rectifying
- Not available in all processes
- Relatively inexpensive adder in some processes
- Lower cut-in voltage than pn junction diode
- High speed

The MESFET

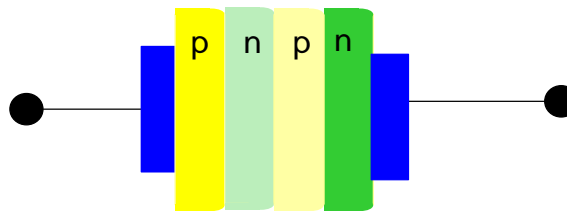
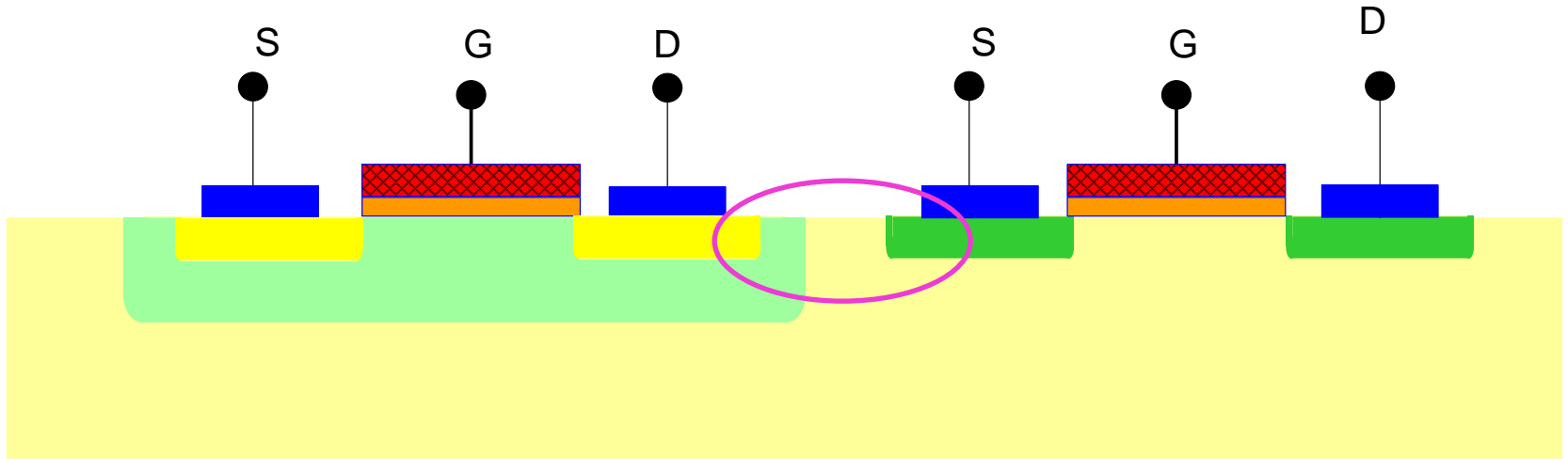


- Metal-Semiconductor Junction for Gate
- Drain and Source contacts ohmic, other is rectifying
- Usually not available in standard CMOS processes
- Must not forward bias very much
- Lower cut-in voltage than pn junction diode
- High speed

The Thyristor

A bipolar device in CMOS Processes

Consider a Bulk-CMOS Process



Have formed a lateral pnpn device !

Will spend some time studying pnpn devices

Outline

Bipolar Processes

- Parasitic Devices in CMOS Processes
- JFET
- Other Junction Devices

Special Bipolar Processes



Thyristors
SCR
TRIAC

Thyristors

The good and the bad!

Thyristors

The good

SCRs

Triacs

The bad

Parasitic Device that can destroy integrated circuits

Outline

Bipolar Processes

- Parasitic Devices in CMOS Processes
- JFET
- Other Junction Devices

Special Bipolar Processes

- Thyristors



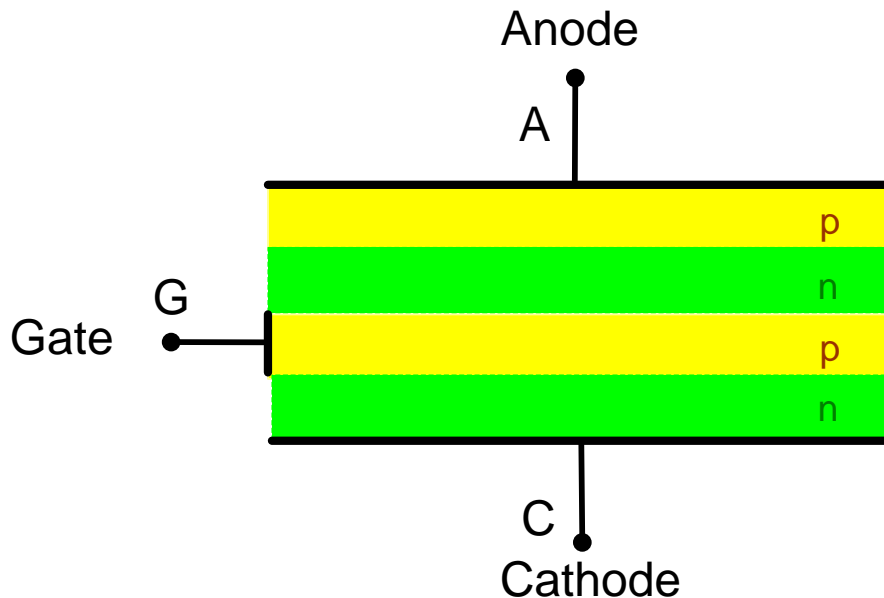
SCR

TRIAC

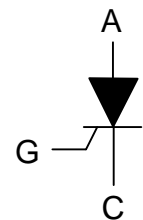
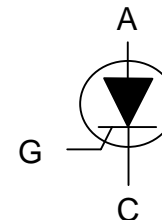
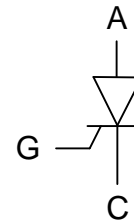
The SCR

Silicon Controlled Rectifier

- Widely used to switch large resistive or inductive loads
- Widely used in the power electronics field
- Widely used in consumer electronic to interface between logic and power



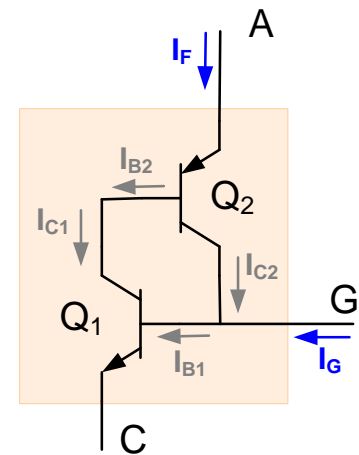
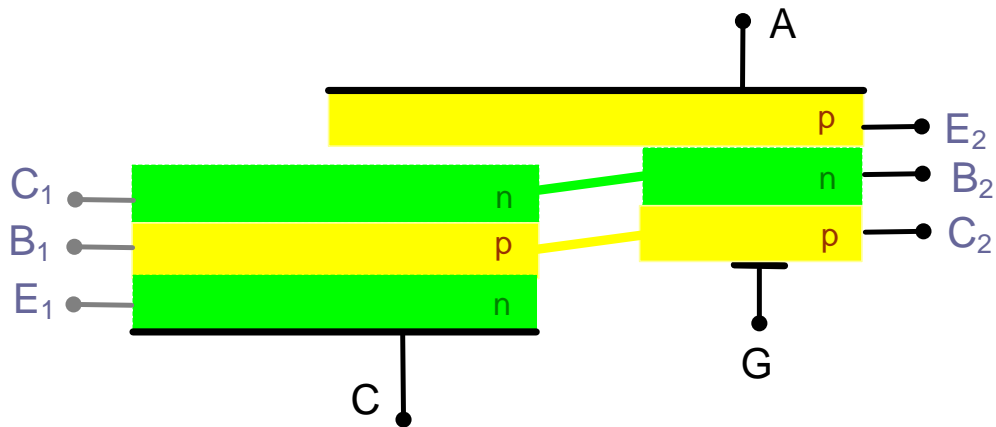
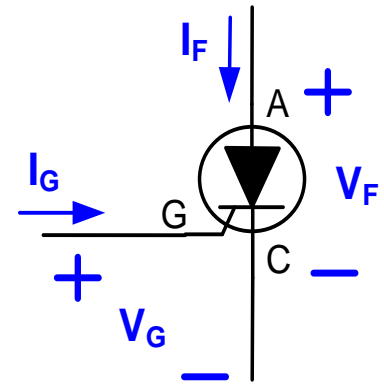
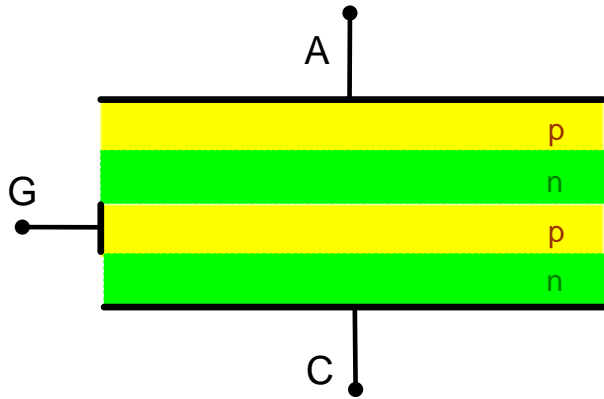
Usually made by diffusions in silicon



Symbols

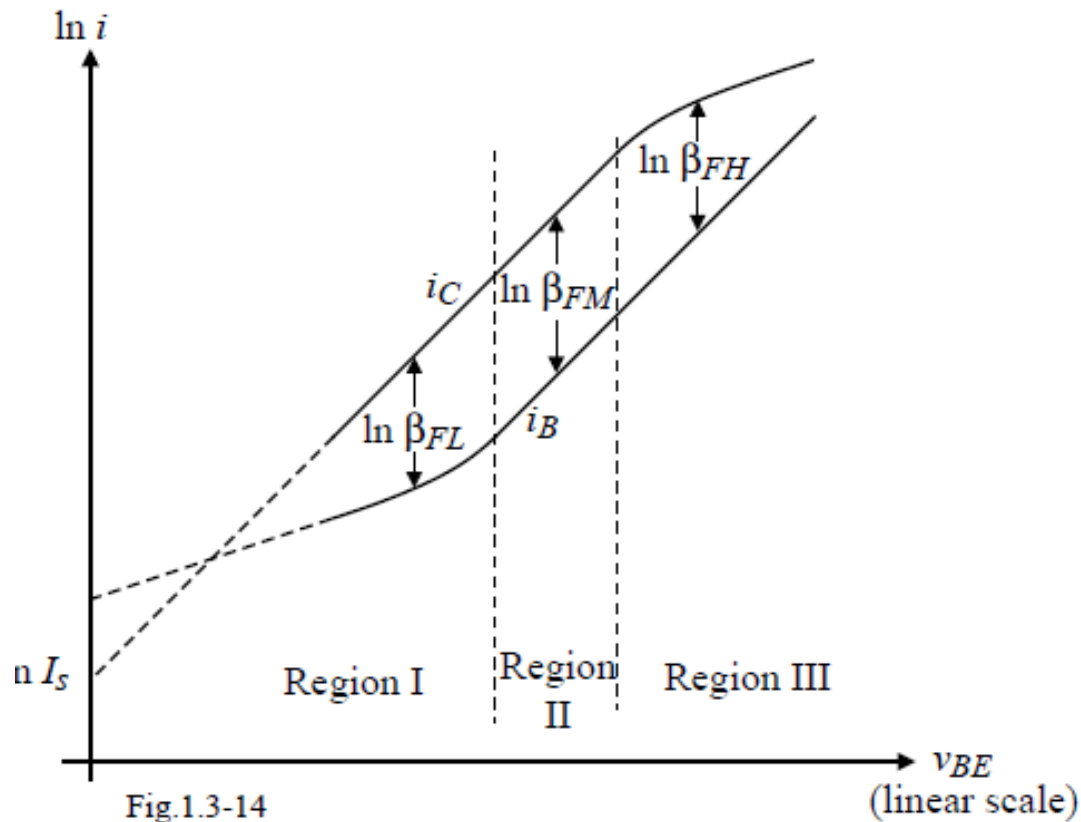
Consider first how this 4-layer 3-junction device operates

Operation of the SCR



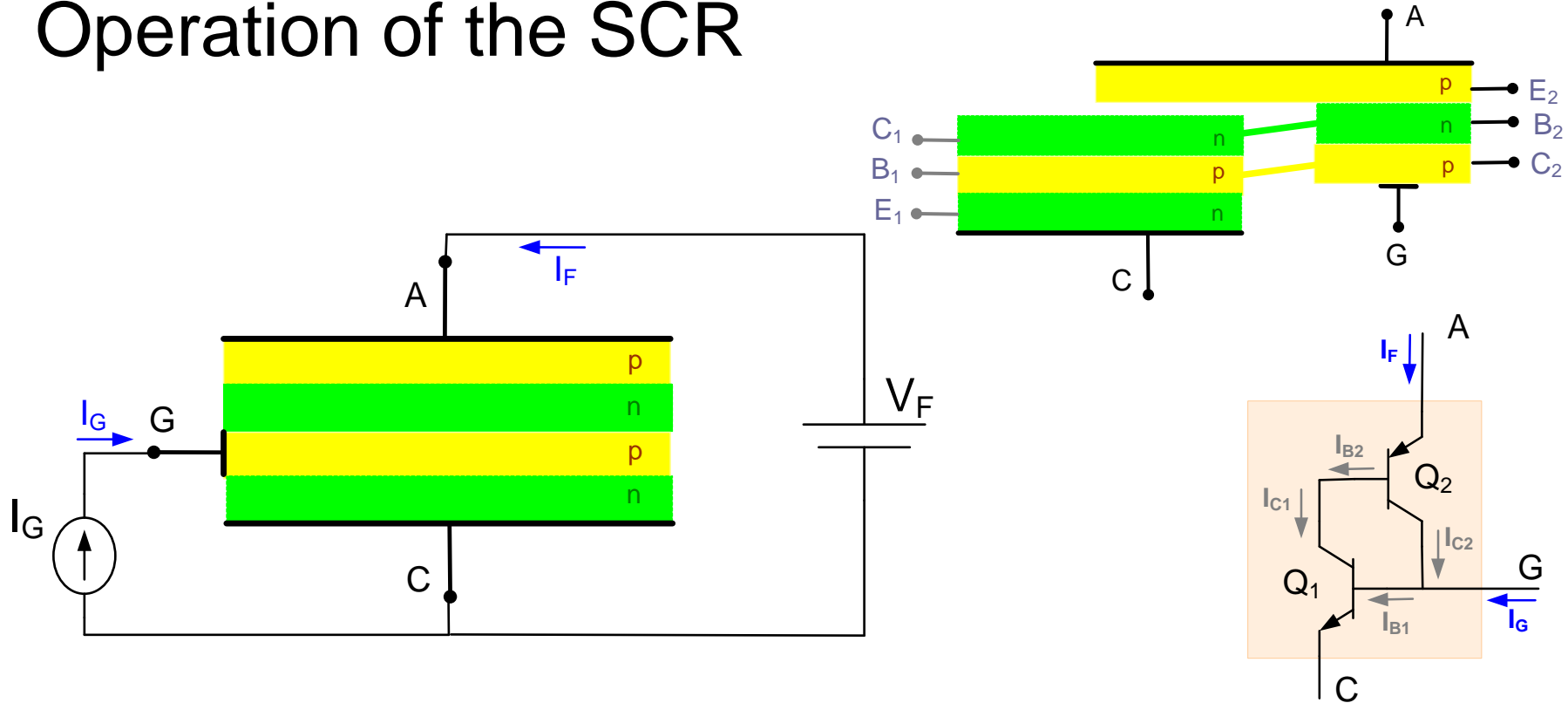
Not actually separated but useful for describing operation

Variation of Current Gain (β) with Bias for BJT



Note that current gain gets very small at low base current levels

Operation of the SCR



Consider a small positive bias (voltage or current) on the gate ($V_{GC} < 0.5V$) and a positive and large voltage V_F

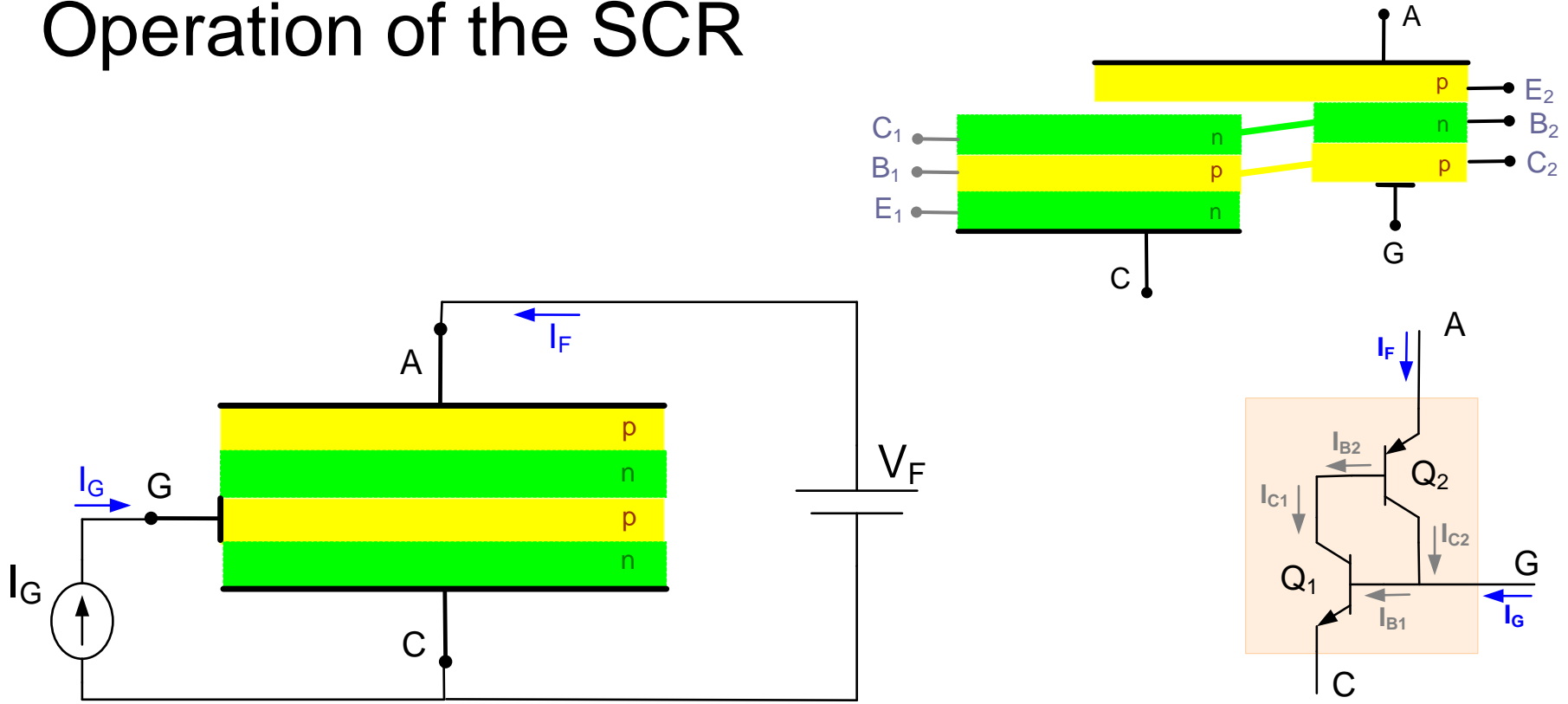
Will have $V_{C1} \geq V_F - 0.5V$

Thus Q_1 has a large positive voltage on its collector

Since $V_{B_{E1}}$ is small, I_{C1} will be small as will I_{C2} so diode equation governs BE junction of Q_1

I_F will be very small

Operation of the SCR



Now let bias on the gate increase (V_{GC} around 0.6V) so Q_1 and Q_2 in FA $V_{C1} \geq V_F - 0.5V$

From diode equation, base voltage V_{BE1} will increase and collector current I_{C1} will increase

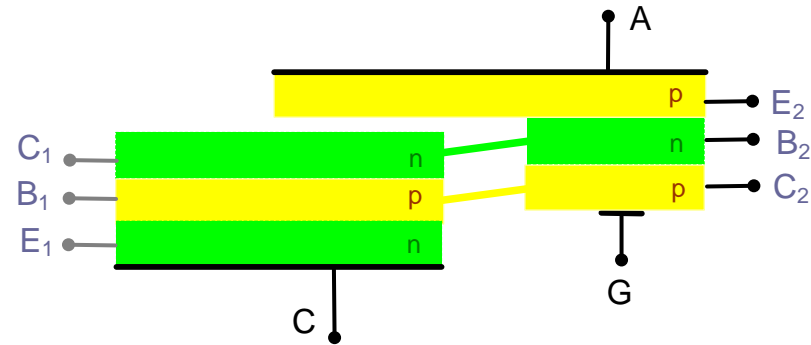
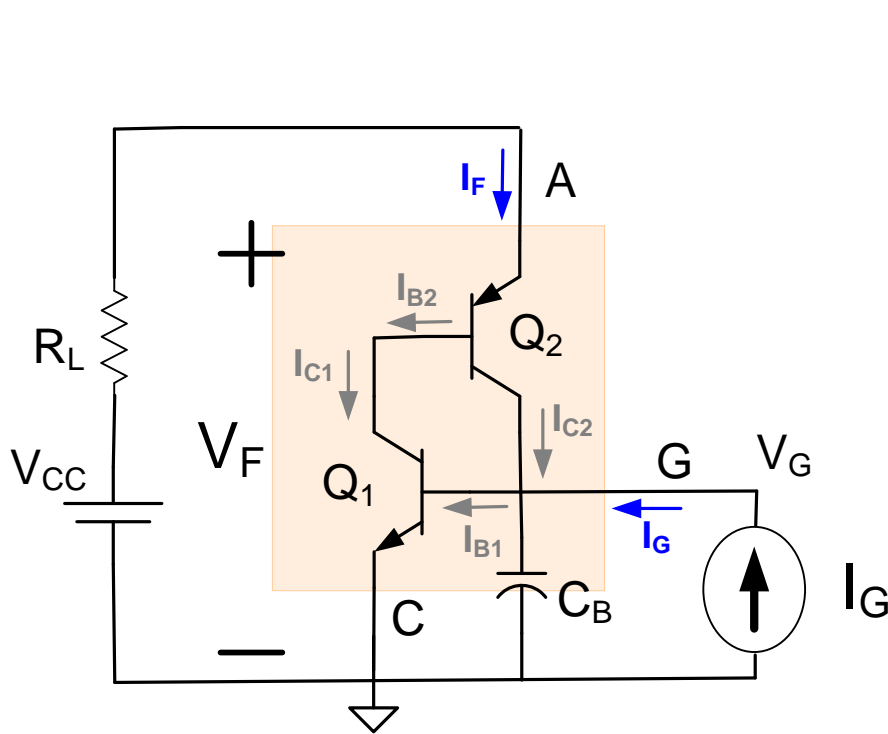
Thus base current I_{B2} will increase as will the collector current of I_{C2}

Under assumption of operation in FA region get expression

$$I_{B1} = I_G + \beta_1 \beta_2 I_{B1}$$

This is regenerative feedback (actually can show pole in RHP)

Very Approximate Analysis Showing RHP Pole



$$V_G s C_B + I_{B1} = I_{C2} + I_G$$

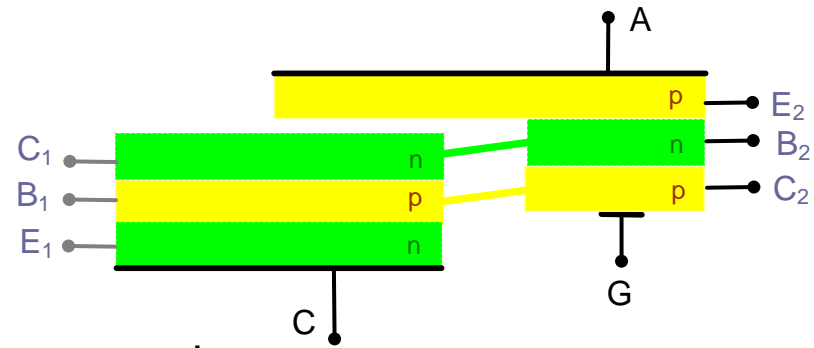
$$I_{C2} = \beta_1 \beta_2 I_{B1}$$

$$I_{B1} R_{BE} = V_G$$

$$V_G = I_G \frac{R_{BE}}{s R_{BE} C_B + 1 - \beta_1 \beta_2}$$

$$p = \frac{\beta_1 \beta_2 - 1}{R_{BE} C_B}$$

Operation of the SCR



$$V_{C1} \cong V_F - 0.6V$$

Under assumption of operation in FA region get expression

$$I_{B1} = I_G + \beta_1 \beta_2 I_{B1}$$

What will happen with this is regenerative feedback?

If I_G is small (and thus β_1 and β_2 are small) I_F will be very small

If I_G larger but less than $\beta_1 \beta_2 I_{B1}$ it can be removed and current will continue to flow

I_{C1} will continue to increase and drive Q_1 into SAT

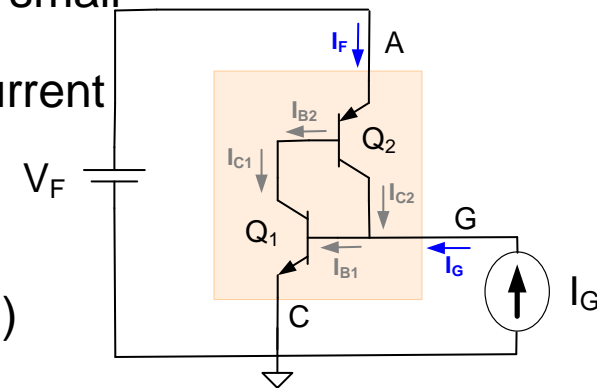
This will try to drive V_A towards 0.9V (but forced to be V_F !)

The current in V_F will go towards ∞

The SCR will self-destruct because of excessive heating !

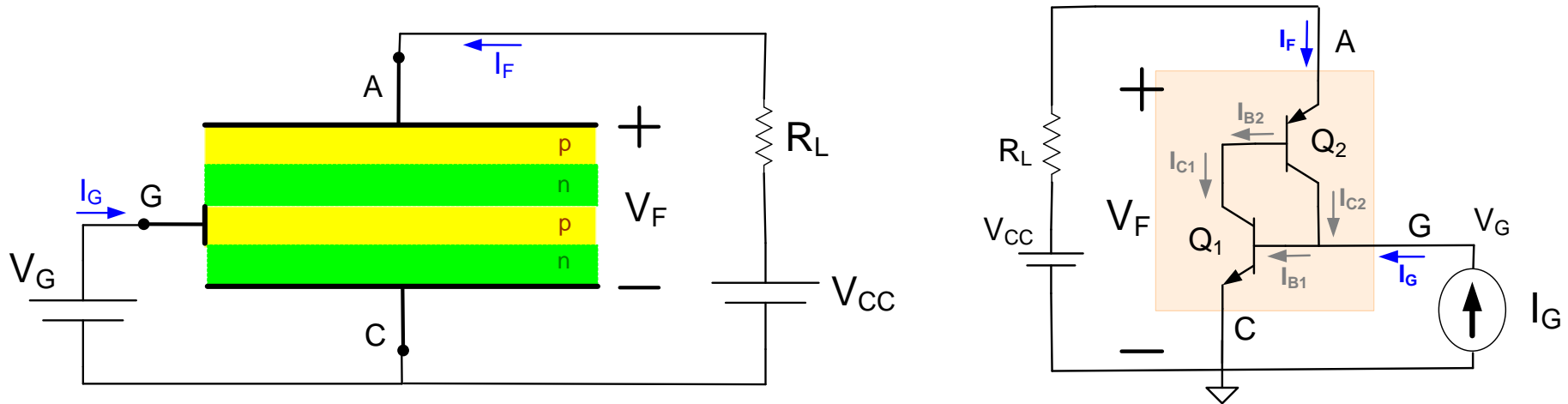


Too bad the circuit self-destructed because the small gate current was able to control a lot of current!



Operation of the SCR

Consider a modified application by adding a load (depicted as R_L)



All operation is as before, but now, after the triggering occurs, the voltage V_F will drop to approximately 0.8 V and the voltage $V_{CC} - 0.8$ will appear across R_L

If V_{CC} is very large, the SCR has effectively served as a switch putting V_{CC} across the load and after triggering occurs, I_G can be removed!

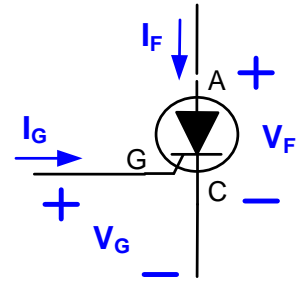
But, how can we turn it off?

Will discuss that later

Operation of the SCR

SCR model

$$\left. \begin{aligned} I_F &= f_1(V_F, V_G) \\ I_G &= f_2(V_G) \end{aligned} \right\}$$



As for MOSFET, Diode, and BJT, several models for SCR can be developed

The Ideal SCR Model

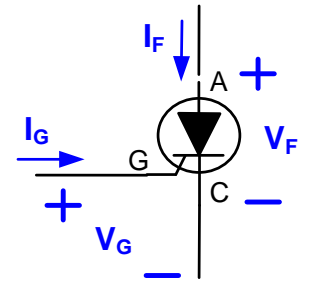
$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$

or

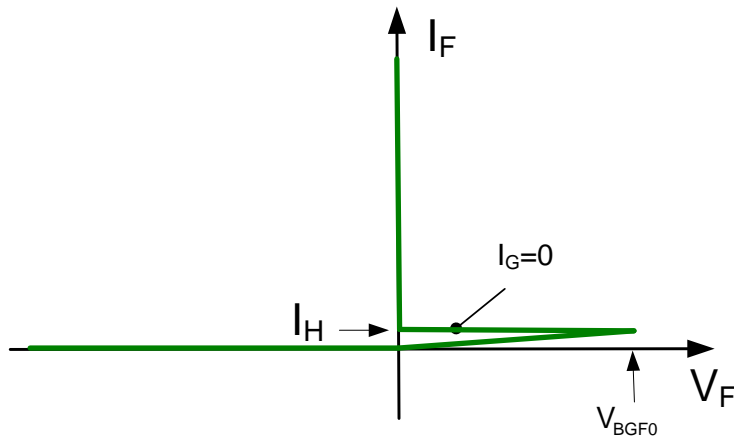
$$\left. \begin{aligned} I_F &= f_{1IA}(V_F, V_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$

Operation of the SCR

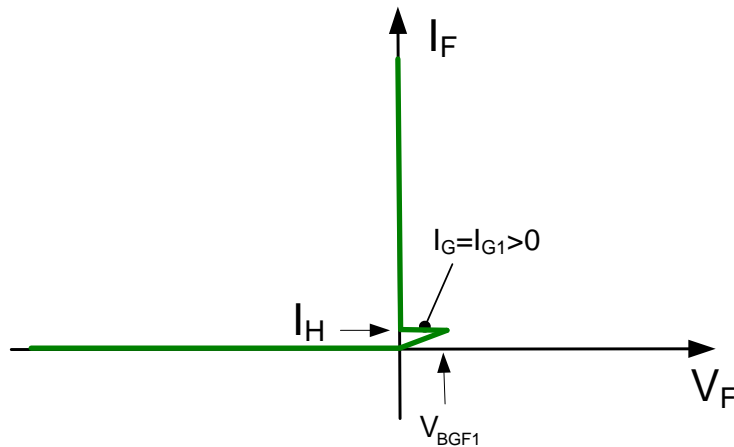
Consider the Ideal SCR Model



$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$



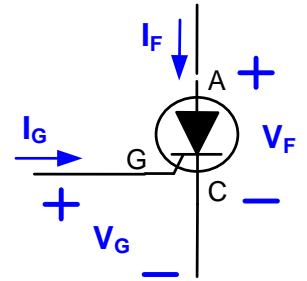
I_H is very small



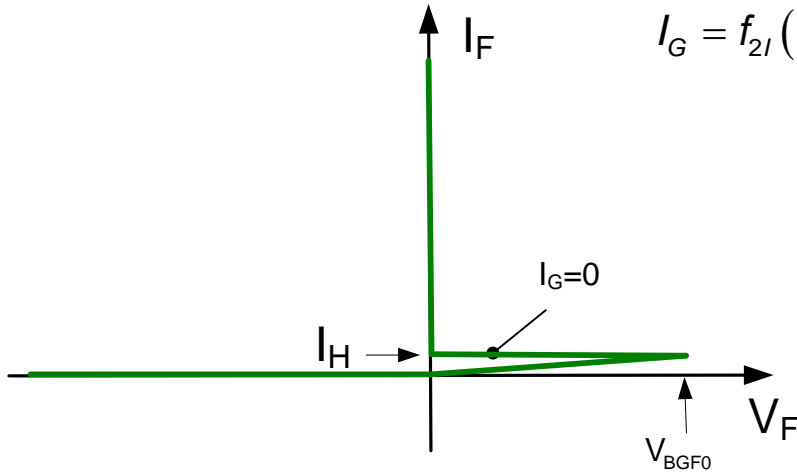
I_{G1} is small (but not too small)

Operation of the SCR

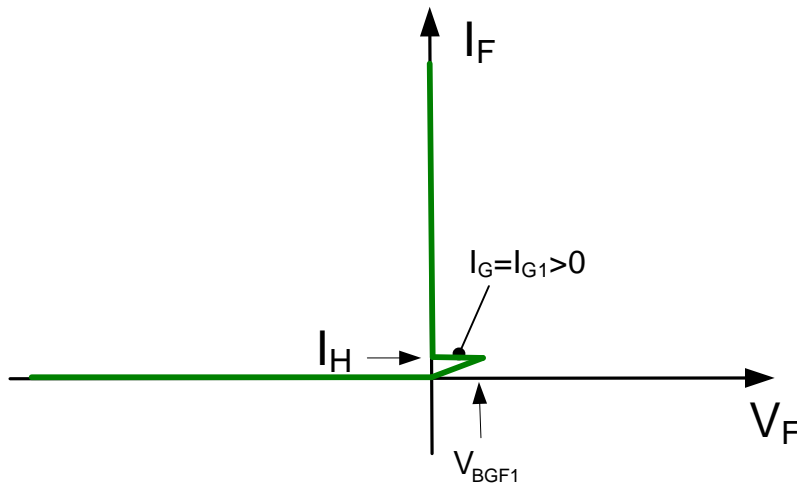
Consider the Ideal SCR Model



$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$



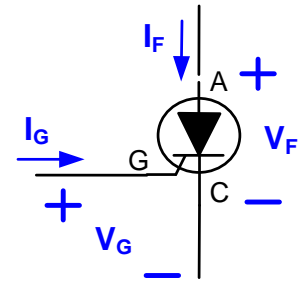
I_H is very small



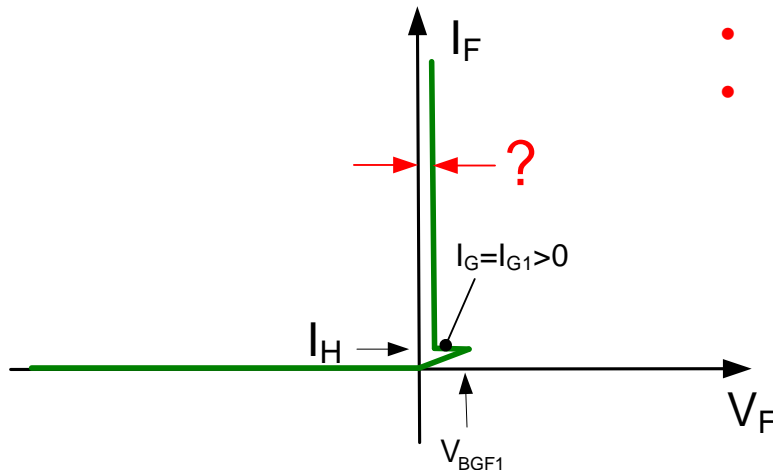
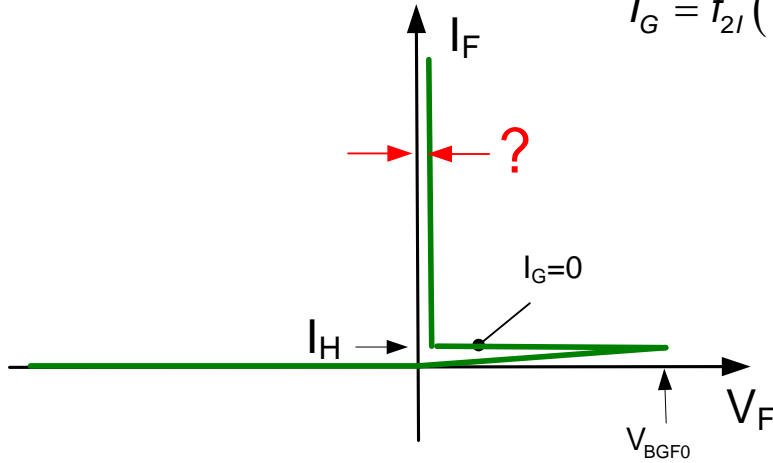
I_{G1} is small (but not too small)

Operation of the SCR

Consider nearly Ideal SCR Model



$$\left. \begin{aligned} I_F &= f_{1I}(V_F, I_G) \\ I_G &= f_{2I}(V_G) \end{aligned} \right\}$$



- On voltage approximately 0.9V
- Major contributor to ON-state power dissipation
- Even with large currents, P_{ON} is quite small

Operation of the SCR

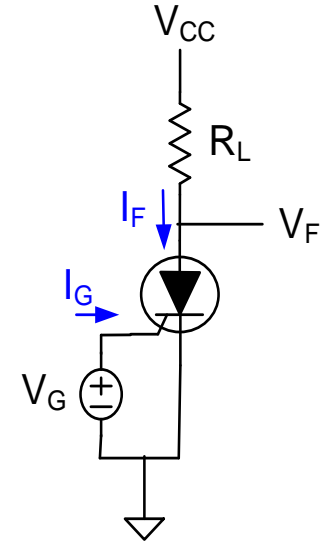
Operation with the Ideal SCR

$$I_F = f_1(V_F, V_G)$$

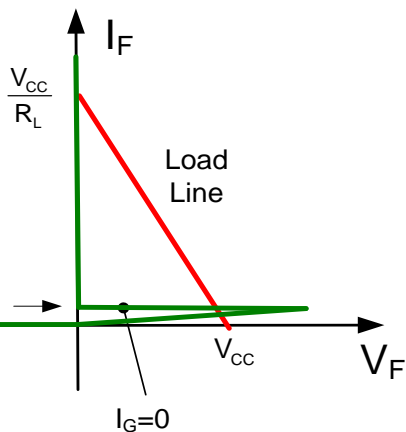
$$I_G = f_2(V_G)$$

Load Line: $V_{CC} = I_F R_L + V_F$

Analysis: $V_{CC} = I_F R_L + V_F$
 $I_F = f_{1I}(V_F, V_G)$



The solution of these two equations is at the intersection of the load line and the device characteristics



when $I_G=0$

Note three intersection points

Two (upper and lower) are stable equilibrium points, one is not

When operating at upper point, $V_F=0$ so V_{CC} appears across R_L We say SCR is ON

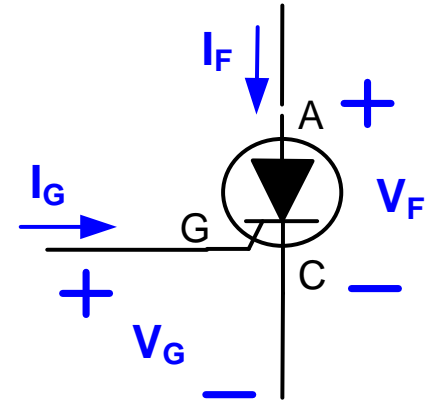
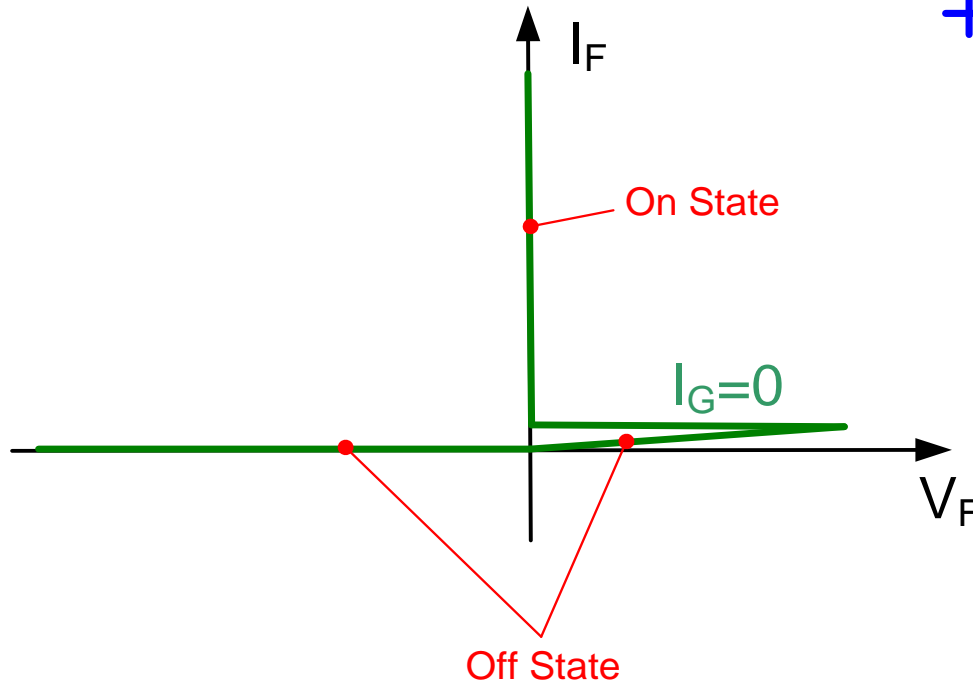
When operating at lower point, I_F approx 0 so no signal across R_L We say SCR is OFF

When $I_G=0$, will stay in whatever state it was in

Operation of the SCR

Operation with the Ideal SCR

$$I_F = f_{11}(V_F, I_G)$$



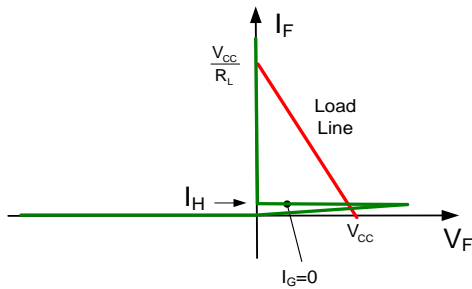
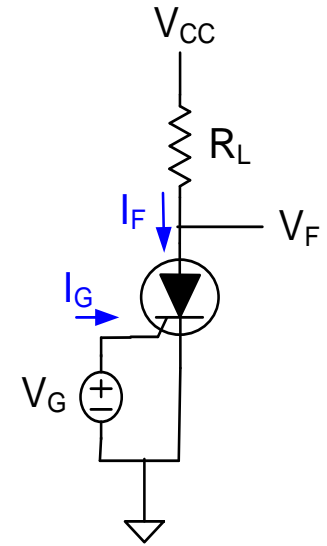
For notational convenience will drop subscript unless emphasis is needed

$$I_F = f_{11}(V_F, I_G) \quad \longrightarrow \quad I_F = f(V_F, I_G)$$

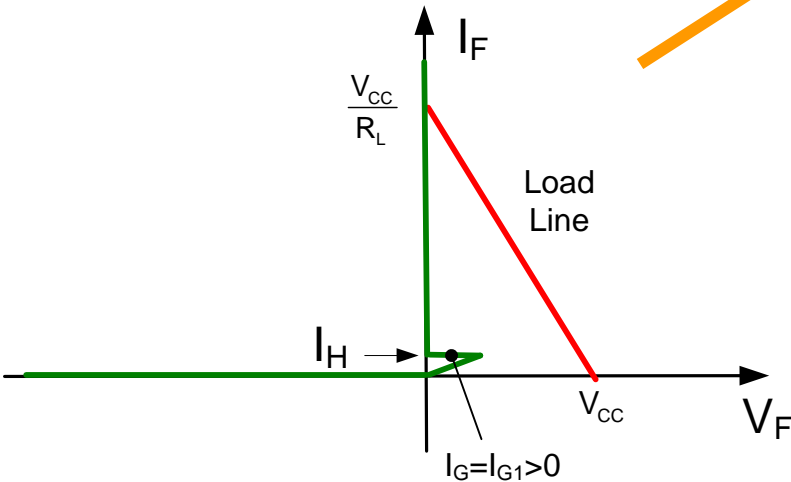
Operation of the SCR

Operation with the Ideal SCR

Now assume it was initially in the OFF state and then a gate current was applied



$$\left. \begin{aligned} V_{CC} &= I_F R_L + V_F \\ I_F &= f(V_F, I_G) \end{aligned} \right\}$$



Now there is a single intersection point so a unique solution

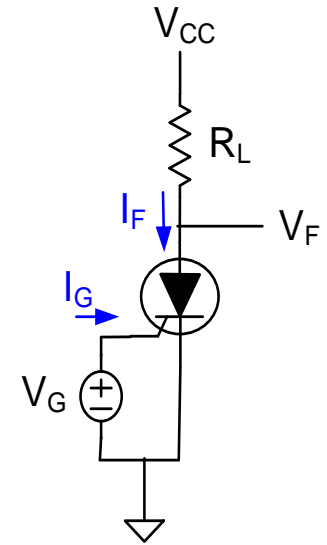
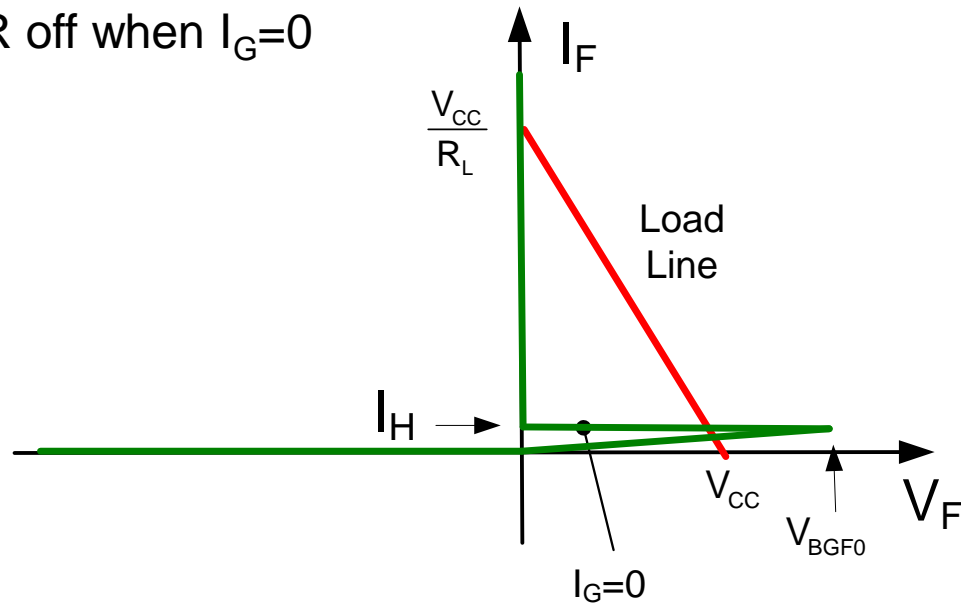
The SCR is now ON

Removing the gate current will return to the previous solution (which has 3 intersection points) but it will remain in the ON state

Operation of the SCR

Operation with the Ideal SCR

Turning SCR off when $I_G=0$



Reduce V_{CC} so that V_{CC}/R_L goes below I_H

This will provide a single intersection point

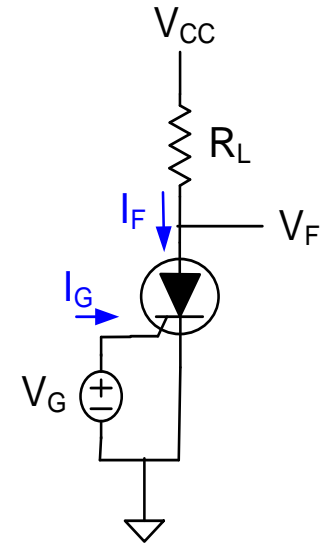
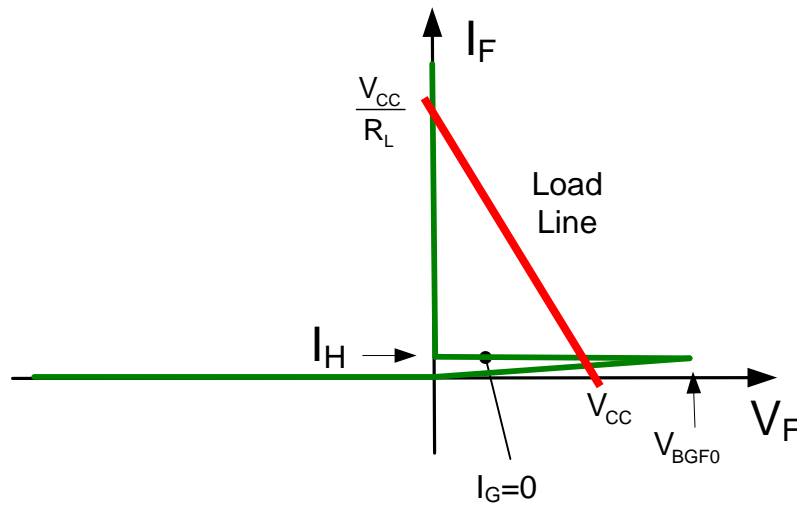
V_{CC} can then be increased again and SCR will stay off

Must not increase V_{CC} much above V_{BGFO} else will turn on

Operation of the SCR

Operation with the Ideal SCR

Turning SCR off when $I_G=0$

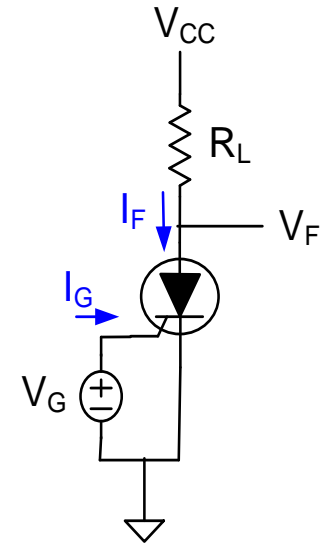
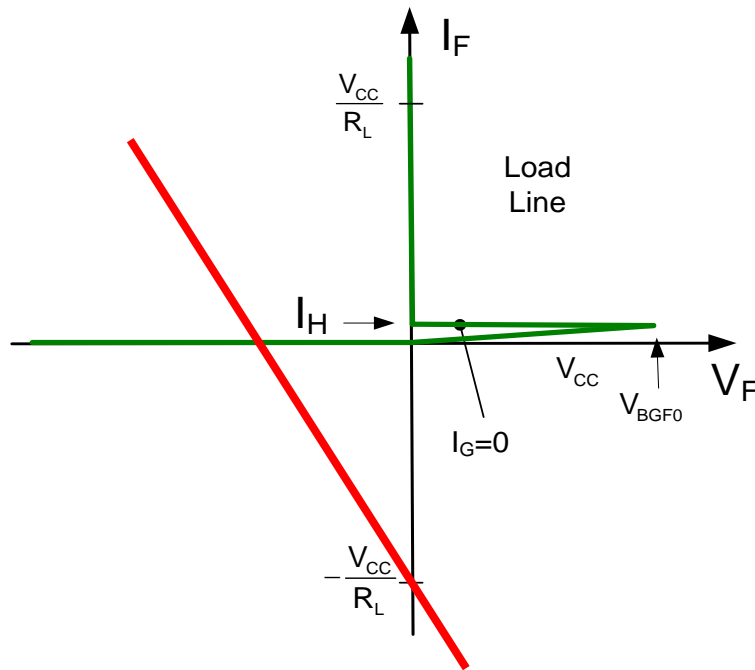


Operation of the SCR

Operation with the Ideal SCR

Often V_{CC} is an AC signal (often 110V)

SCR will turn off whenever AC signal goes negative

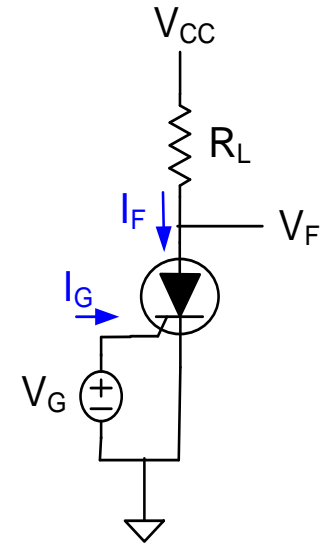
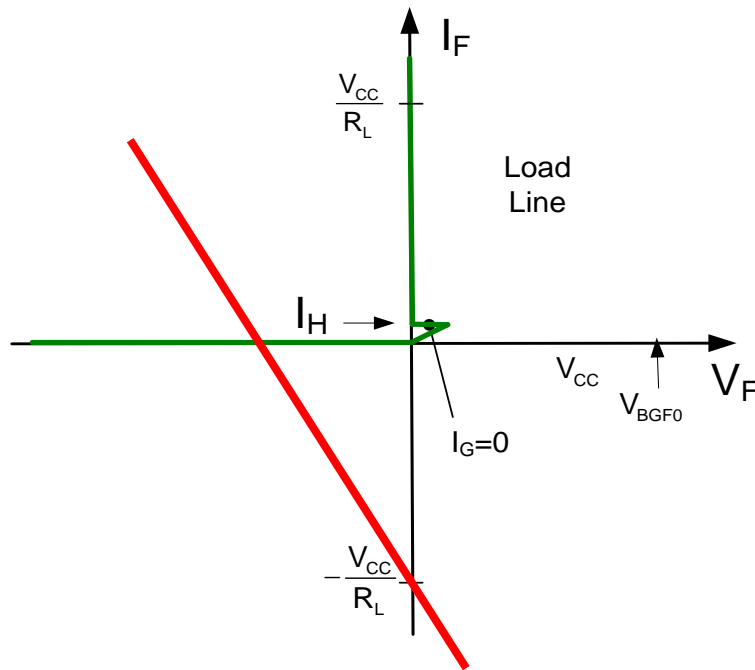


Operation of the SCR

Operation with the Ideal SCR

Often V_{CC} is an AC signal (often 110V)

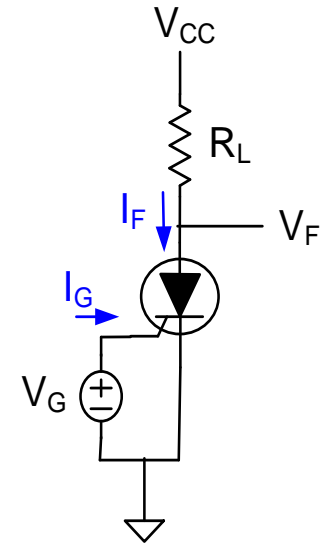
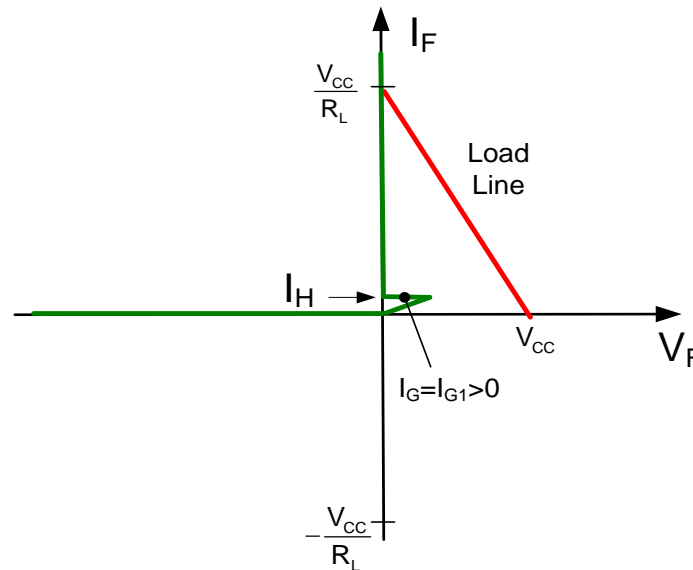
SCR will turn off whenever AC signal goes negative



Operation of the SCR

Operation with the Ideal SCR

Turning SCR off when $I_G > 0$



Reduce V_{CC} so that V_{CC}/R_L goes below I_H

This will provide a single intersection point

But when V_{CC} is then increased SCR will again turn on

Will not turn off if I_G is very large



Stay Safe and Stay Healthy !

End of Lecture 29